



Extremely Time-consuming Project Presentation

2023.5.15

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Fiber Optic Communication

APD Area Review

Paper Reproduction





APD Area Review

Noise and Main parameters

$\text{In}_{0.53}\text{Ga}_{0.47}\text{As}$

SACM APD

Ge/Si APD

Reduce the thickness of the multiplier layer

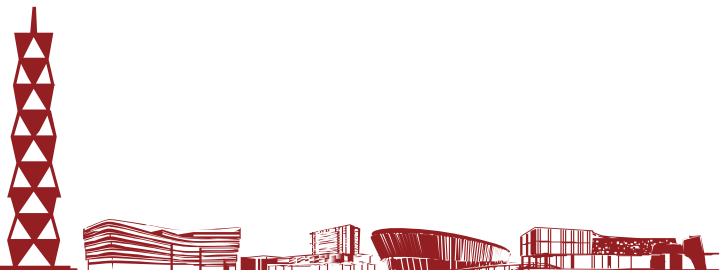
$\text{In}_{0.52}\text{Al}_{0.48}\text{As}$

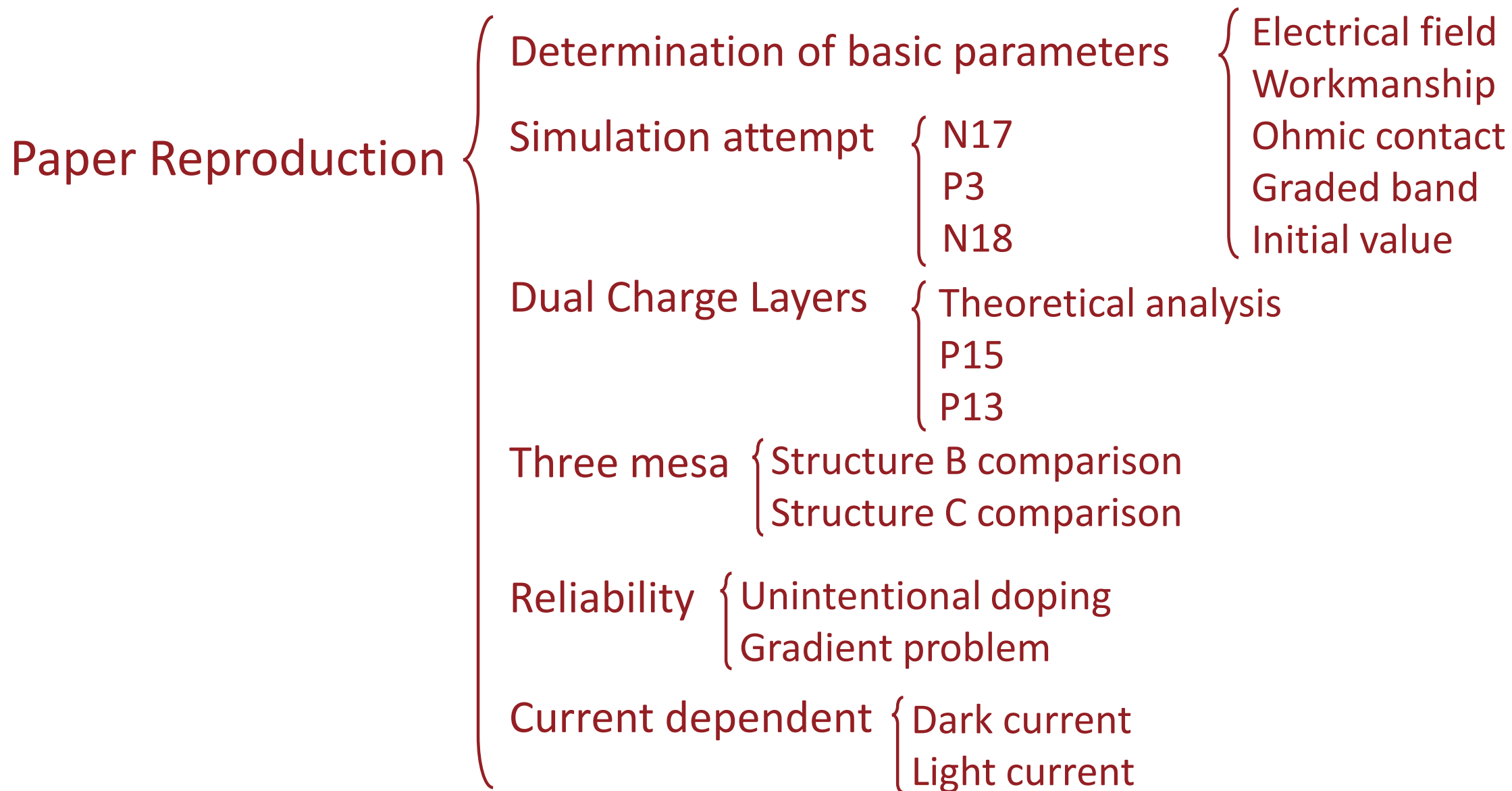
Three mesa

Two-layer absorption

Impact Ionization Engineering

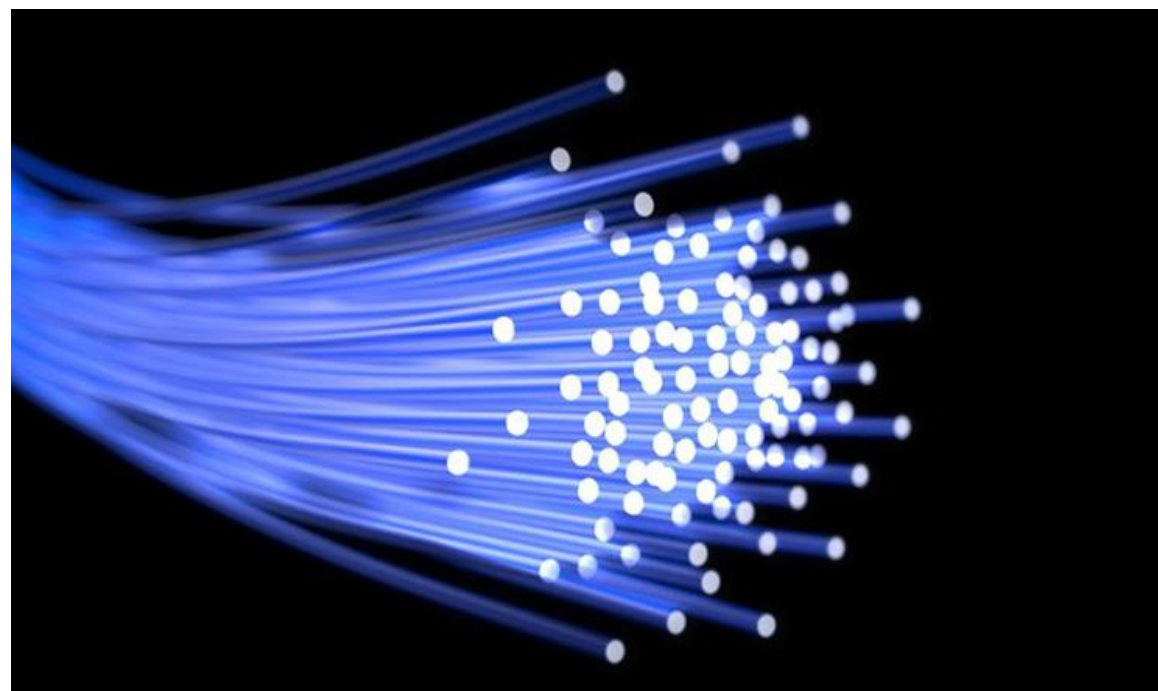
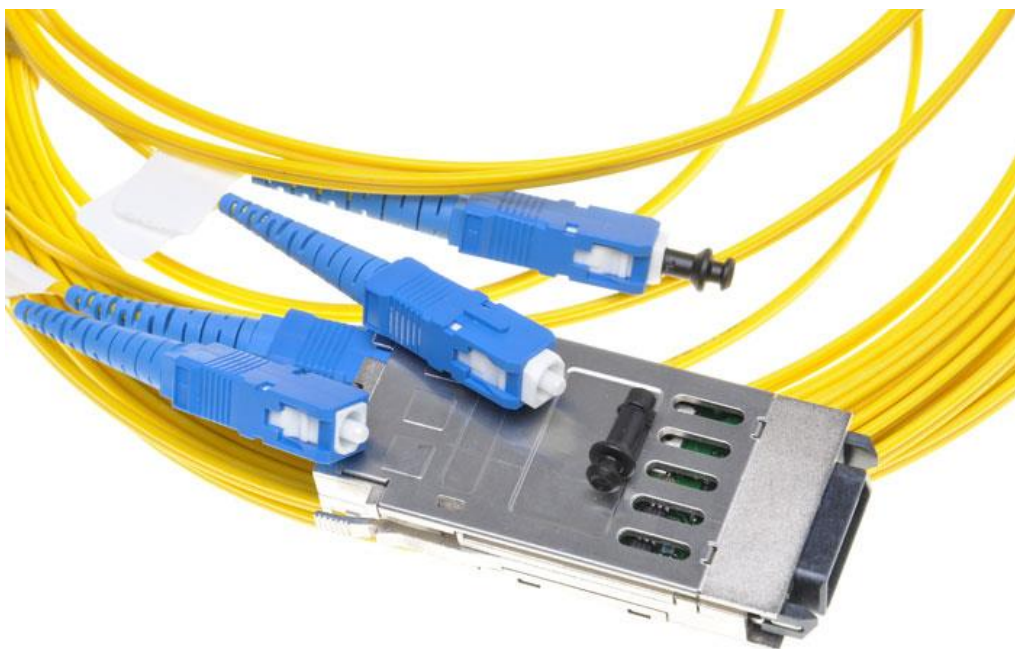
Longer wavelength







Fiber Optic Communication





Reducing loss





Silicon Dioxide



SiO_2 absorption

optical transparency

mechanical strength

electromagnetic interference resistance

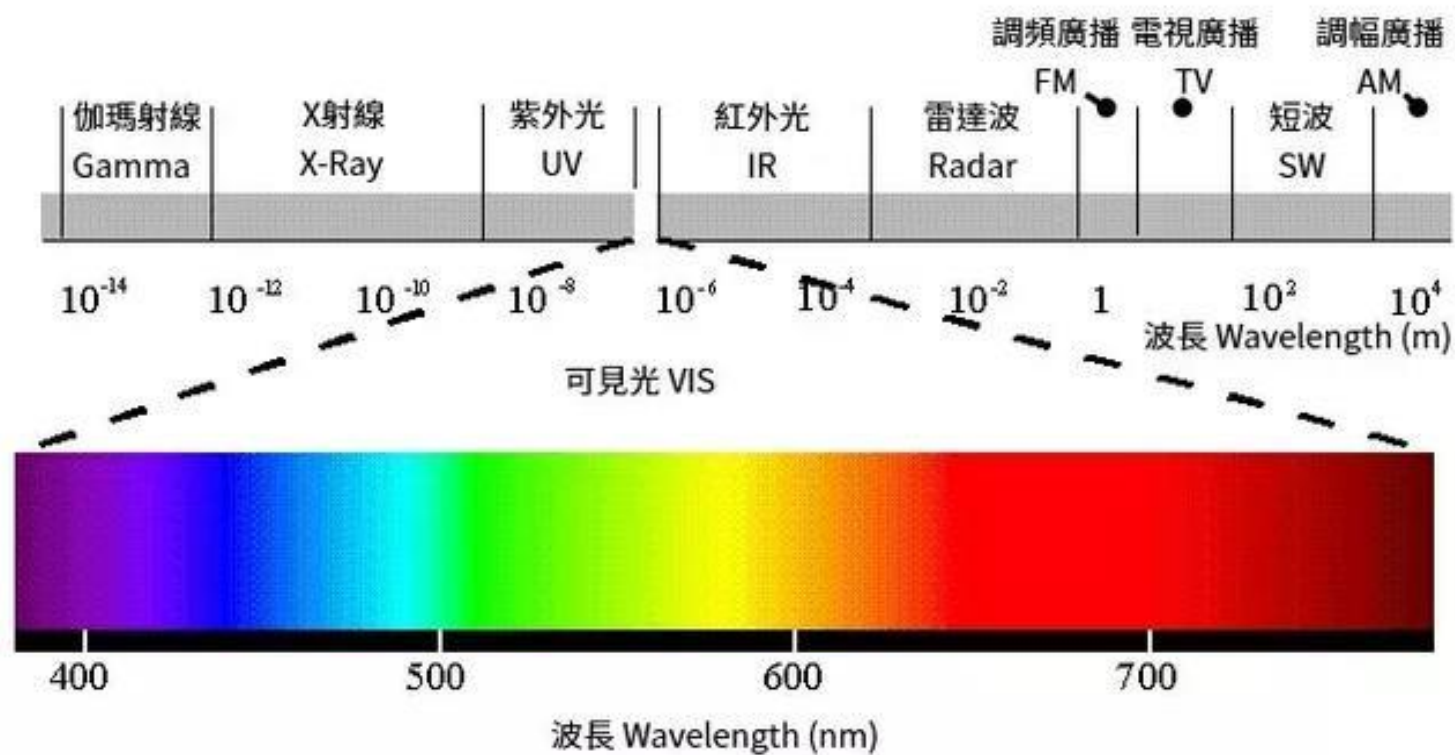
cost-effectiveness

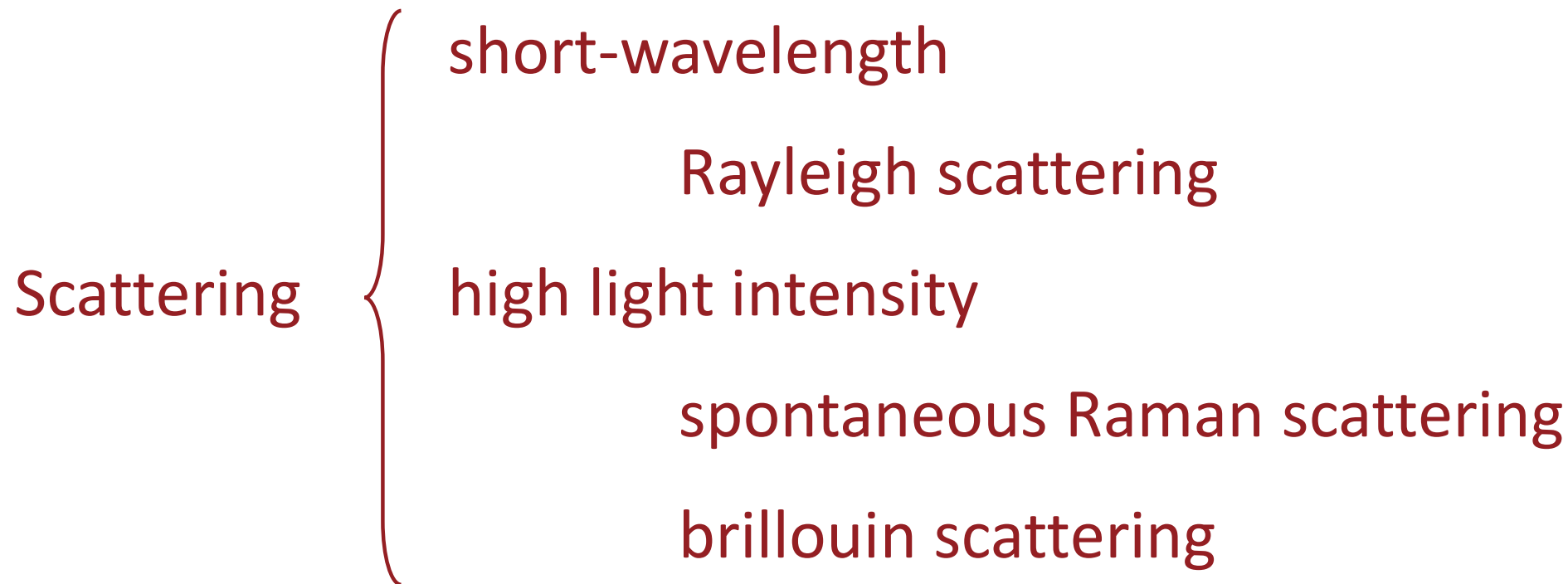


SiO₂ light
absorption

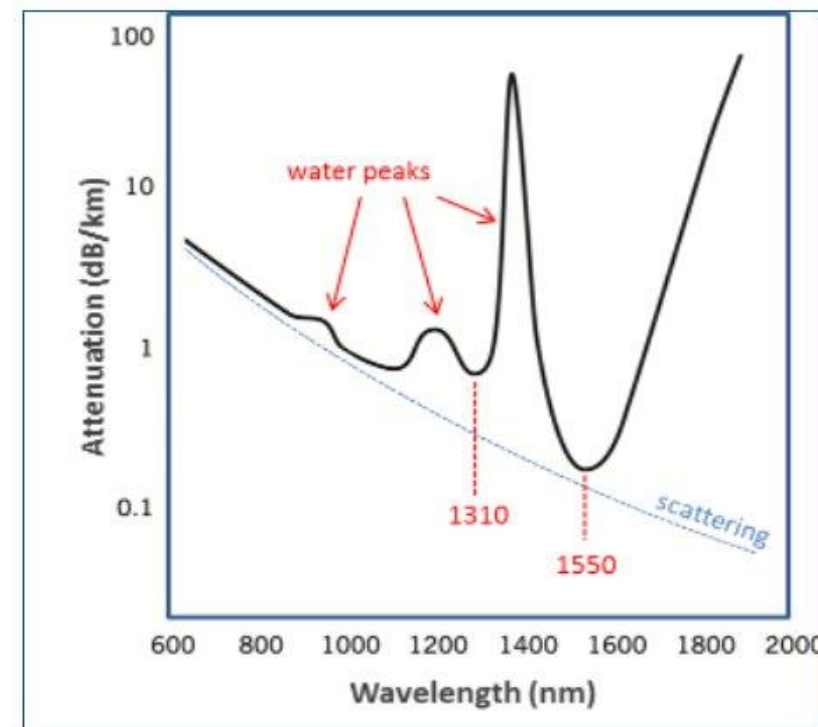
bonding electrons

vibration mode of the Si-O bond network





water vapor light absorption



- [1] Carter, G.A. (1993). "Relationship of leaf spectral reflectance to chloroplast water content determined using NMR microscopy". *Remote Sensing of Environment*. 46 (3): 305–310.
- [2] Rossel, R.A.V. (1998). "Laboratory evaluation of a proximal sensing technique for simultaneous measurement of soil clay and water content". *Geoderma*. 85 (1): 19–39.



APD Area Review

Noise and Main parameters

$\text{In}_{0.53}\text{Ga}_{0.47}\text{As}$

SACM APD

Ge/Si APD

Reduce the thickness of the multiplier layer

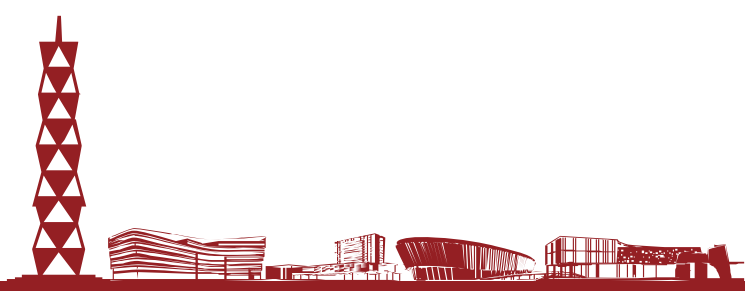
$\text{In}_{0.52}\text{Al}_{0.48}\text{As}$

Three mesa

Two-layer absorption

Impact Ionization Engineering

Longer wavelength



Recent Advances in Avalanche Photodiodes

Joe C. Campbell, *Fellow, IEEE*

(Invited Paper)



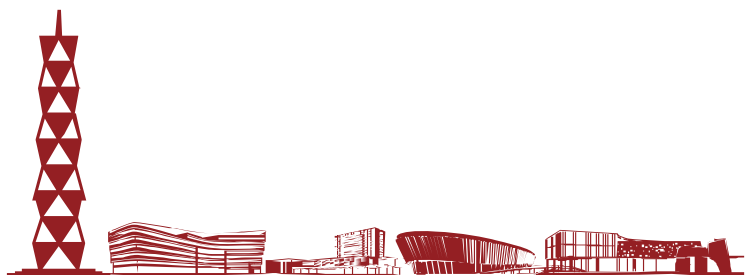


Performance Index



Noise { Thermal noise
Particle noise

Core Index { Gain
Bandwidth
Gain-bandwidth product
Excess noise factor





Advantage

Bandgap: 0.79eV

$$0.79eV \approx \frac{hc}{e \cdot 1510nm}$$

Lattice constant: 5.868Å

matching well with InP

[4] Cook, L. W. Electron and hole impact ionization coefficients in InP determined by photomultiplication measurements[J]. Applied Physics Letters, 1982, 40(7): 589-591.

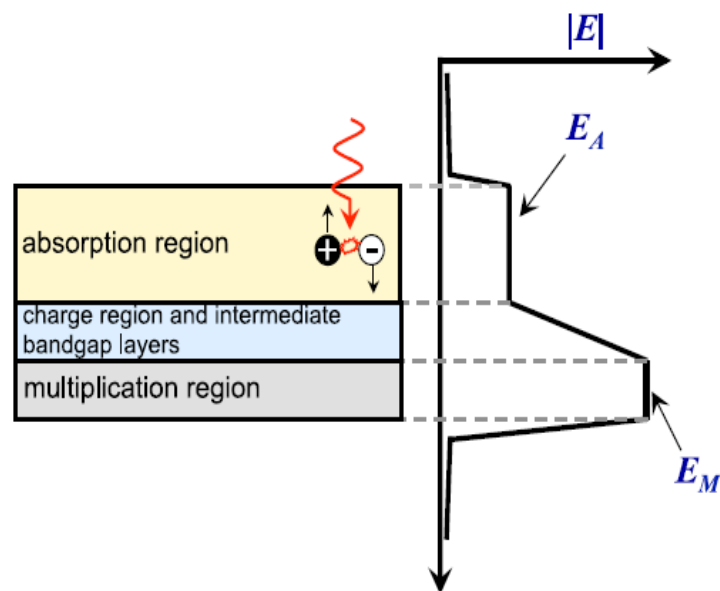




InP {
Low dark current
Pure hole carrier
Low noise

$$I = \frac{(2m^*)^{1/2} q^3 E V A}{4\pi^2 \hbar^2 \epsilon_g^{1/2}} \exp\left(-\frac{\theta m_0^{1/2} \epsilon_g^{3/2}}{q \hbar E}\right).$$





relatively weak absorption efficiency



an absorption layer of at least $2.5\ \mu\text{m}$



longer transition time



lower Gain–bandwidth product



Disadvantage

- low Gain–bandwidth product
- Produce more noise than Si
- Cannot be integrated with the silicon based CMOS process
- Expensive
- Poor crystal quality
- Complex manufacturing process

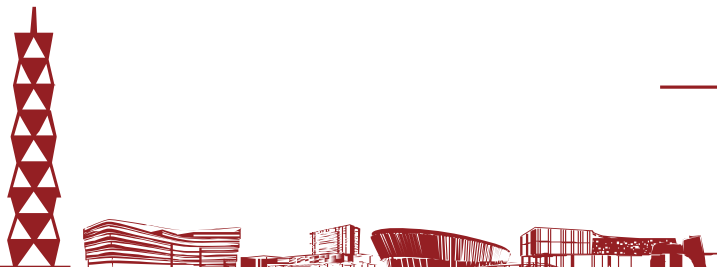




Absorption region Ge

Multiplication region Si {
Wavelength is calculated to be 1.1 μm
Low absorption efficiency near the cutoff wavelength
Lattice mismatch

[5] Shah V A, et al. Effect of layer thickness on structural quality of Ge epilayers grown directly on Si(001)[J]. Thin Solid Films, 2011, 519(22): 7911-7917.





Lattice Mismatch



Lattice mismatch

Rough surface of Ge

High density of dislocation defects

Dark current

Power consumption

Noise

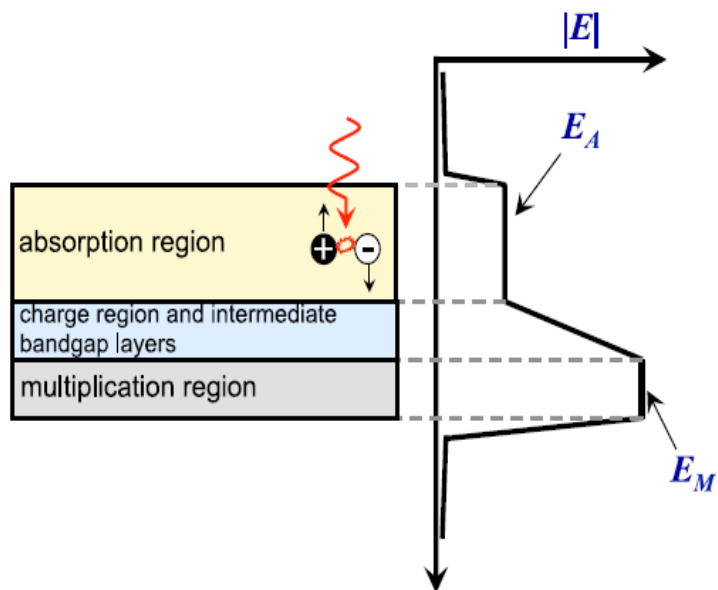
[6] Masini G, et al. High responsivity near infrared Ge photodetectors integrated on Si[J]. Electronics Letters, 1999, 35(17): 1467-1468.

[7] Wei Y, et al. Analysis of dark current dependent upon threading dislocations in Ge/Si heterojunction photodetectors[J]. Microelectronics International, 2012, 29(3): 136-140.





Multiplication layer thickness



$$l = \tau \cdot v \approx 43nm$$





In_{0.52}Al_{0.48}As



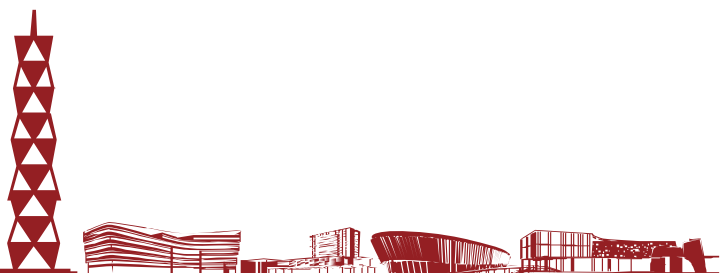
$$I = \frac{(2m^*)^{1/2} q^3 E V A}{4\pi^2 \hbar^2 \epsilon_g^{1/2}} \exp\left(-\frac{\theta m_0^{1/2} \epsilon_g^{3/2}}{q \hbar E}\right).$$

bandgap 1.437 eV

matching lattice constant

Replace InP
As multiplication layer

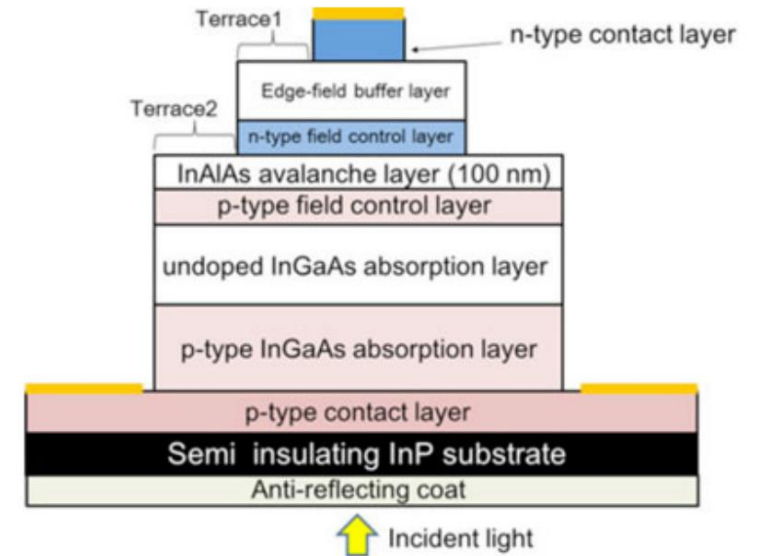
Reduce noise





Three mesa

high electric field region is limited to the space directly below the top surface
avoiding the need for a guard ring
reduces the electric field at the edges
preventing edge breakdown and surface current leakage





Two absorption region



partially depleted p+
+
i-type depleted

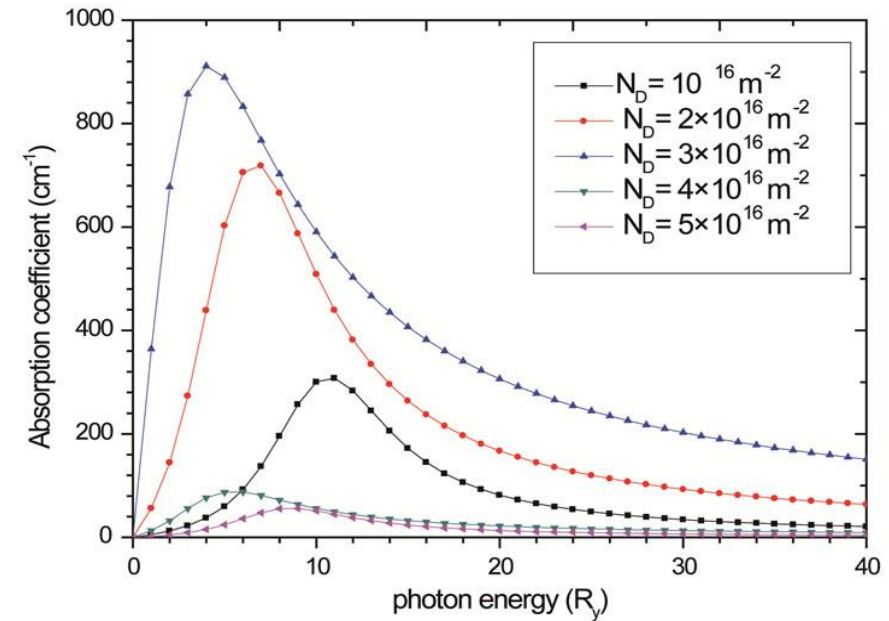
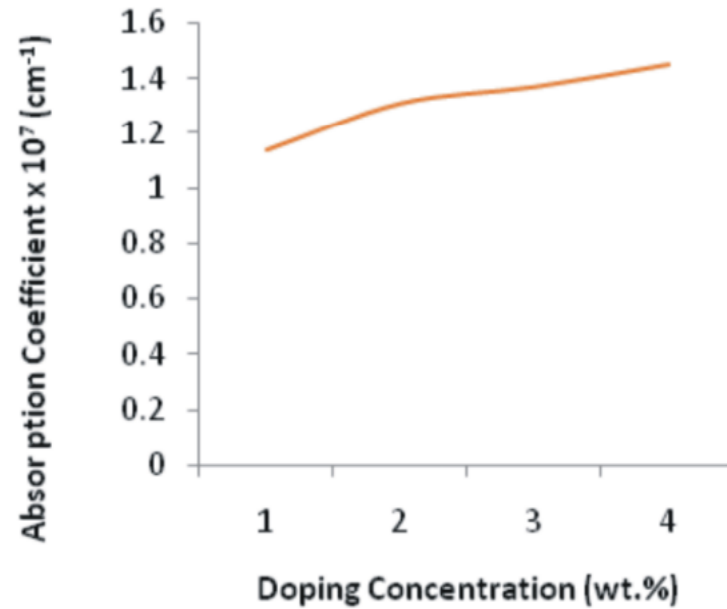
Increasing electric field

Enlarging gain

Increasing absorption efficiency



Two absorption region

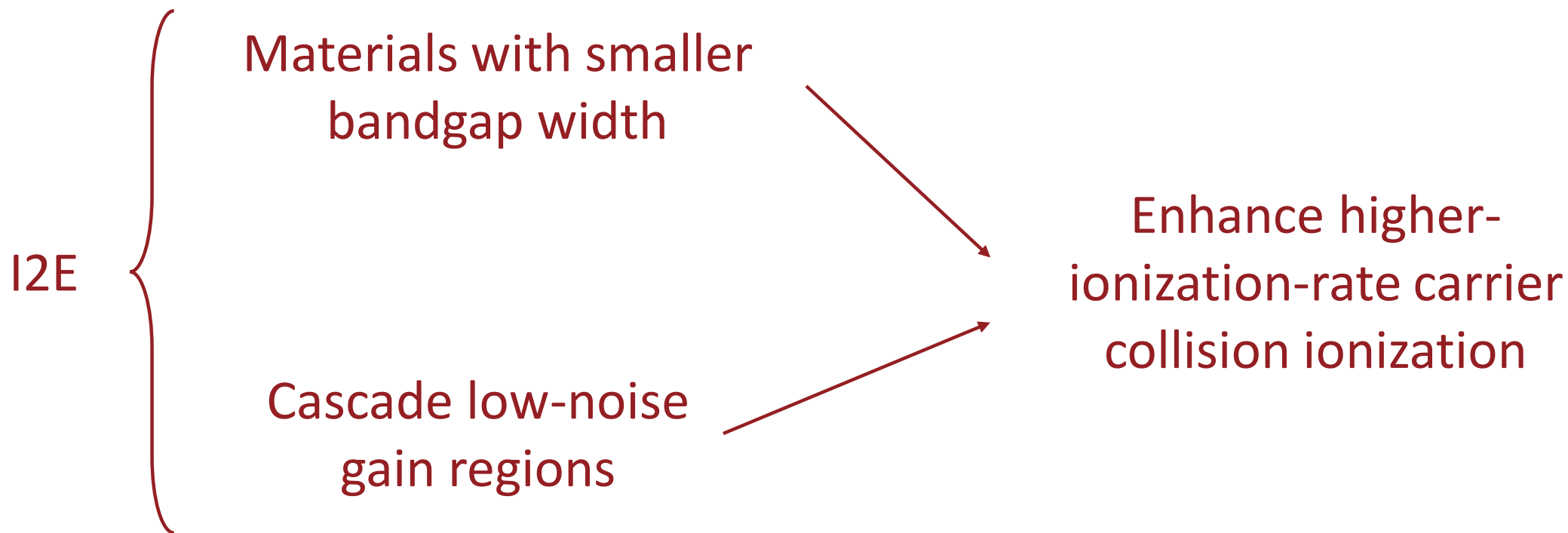


[8] Alpha, M. & Daniel, Thomas. (2015). Effect of Doping Concentration on the Electrical and Optical Properties of Zn: SnO 2. IOSR Journal of Applied Physics. 7. 38-44. 10.9790/4861-07323844..

[9] Dakhlaoui, H. (2012) Effect of the Doping Layer Concentration on Optical Absorption in Si δ -Doped GaAs Layer. Optics and Photonics Journal, 2, 140-144. doi: 10.4236/opj.2012.23020.



Impact Ionization Engineering





Bigger Wavelength



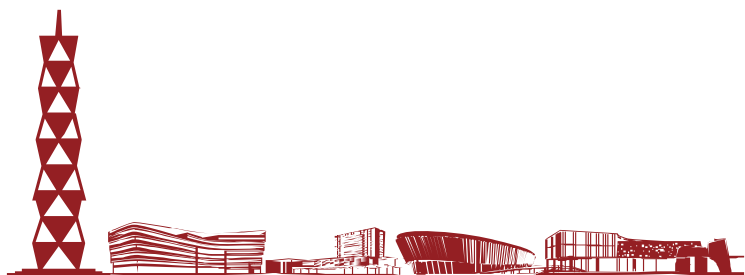
Capacity crunch



Increasing the bandwidth of optical
fiber transmission system



More data can be transmitted on
same infrastructure





Bigger Wavelength



上海科技大学
ShanghaiTech University

WDM

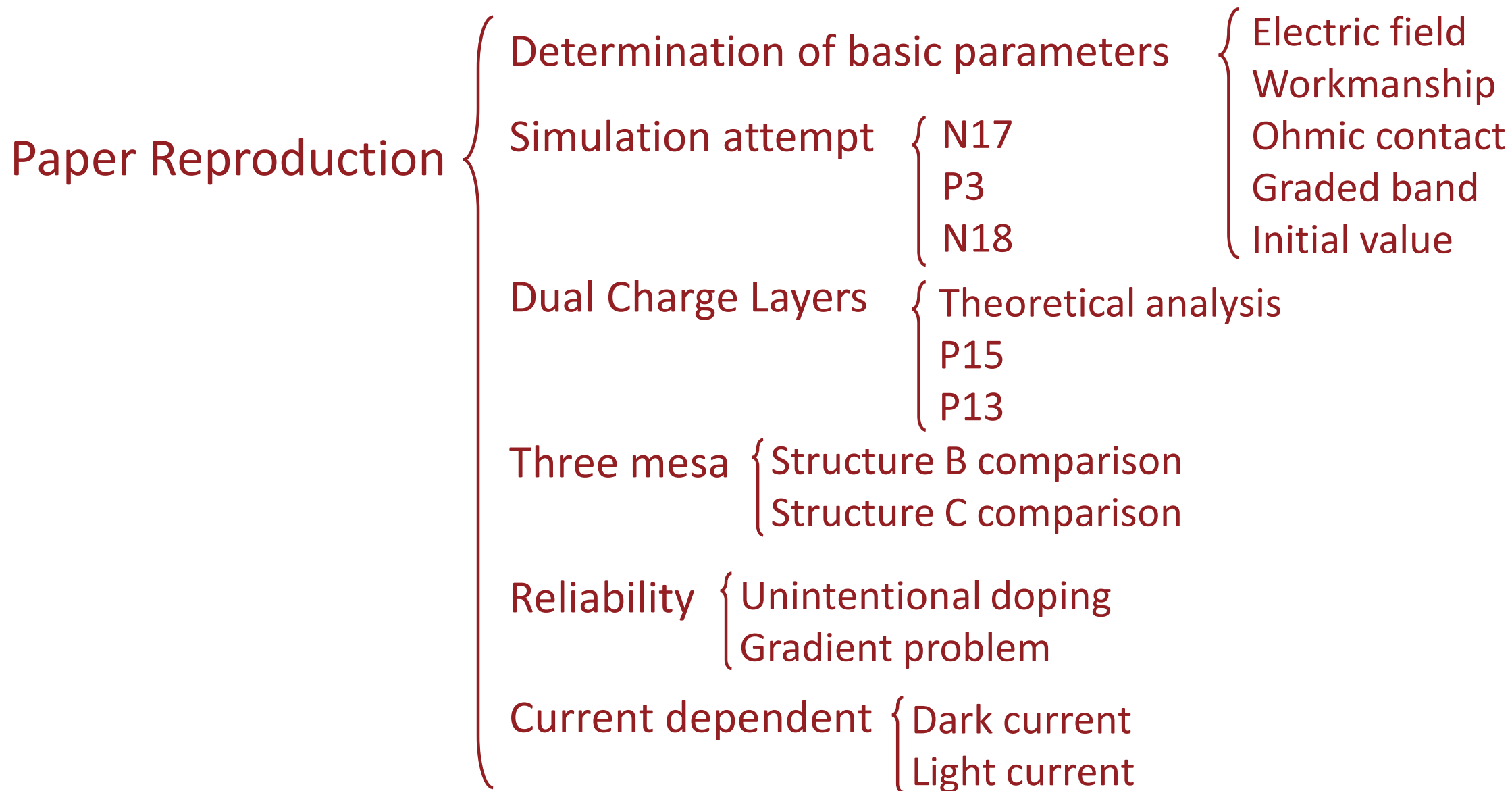
(Wavelength Division Multiplexing)

Higher transmission capacity

Improving data transmission efficiency



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Electrical field

$\text{In}_{0.52}\text{Al}_{0.48}\text{As}$

$\epsilon_s \approx 12.46\epsilon_0$

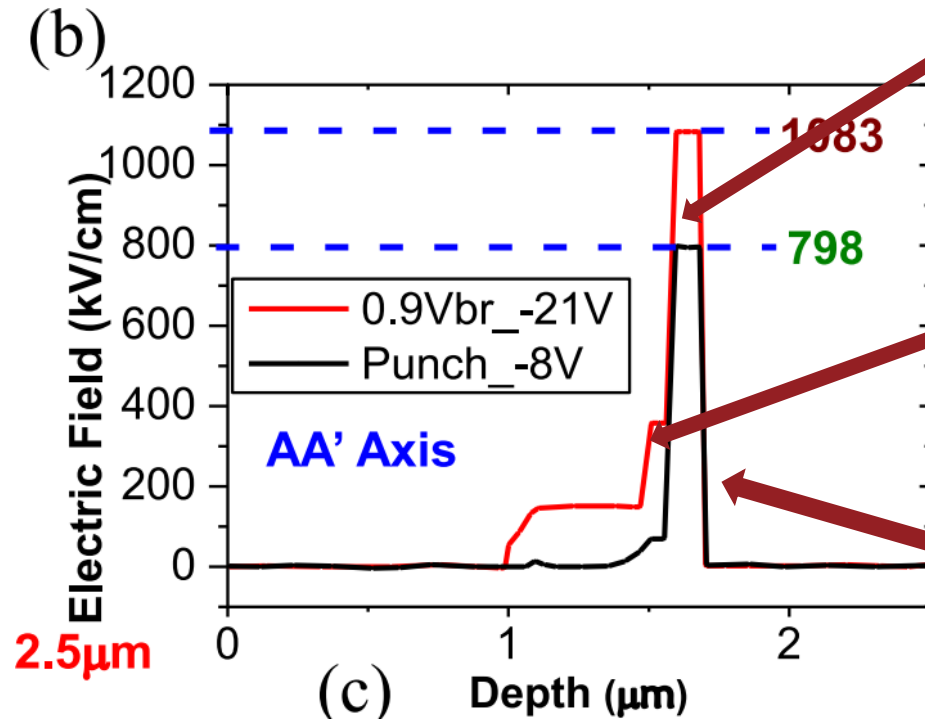
$$\frac{eN_{p13}}{\epsilon} \approx \frac{200\text{kV/cm}}{30\text{nm}}$$

$$\Rightarrow N_{p13} \approx 4.5905e17$$

$$\frac{eN_{p15}}{\epsilon} \approx \frac{700\text{kV/cm}}{30\text{nm}}$$

$$\Rightarrow N_{p15} \approx 1.6067e18$$

$$N_{n17} \geq N_{p15} \approx 1.6067e18$$



[10] M. Littlejohn, K. Kim, and H. Tian, "High-Field Transport in InGaAs and Related Heterostructures," in Bhattacharya, section 4.2, pp. 107-116.



IntelliEPI: InP-based Production MBE HBT Development

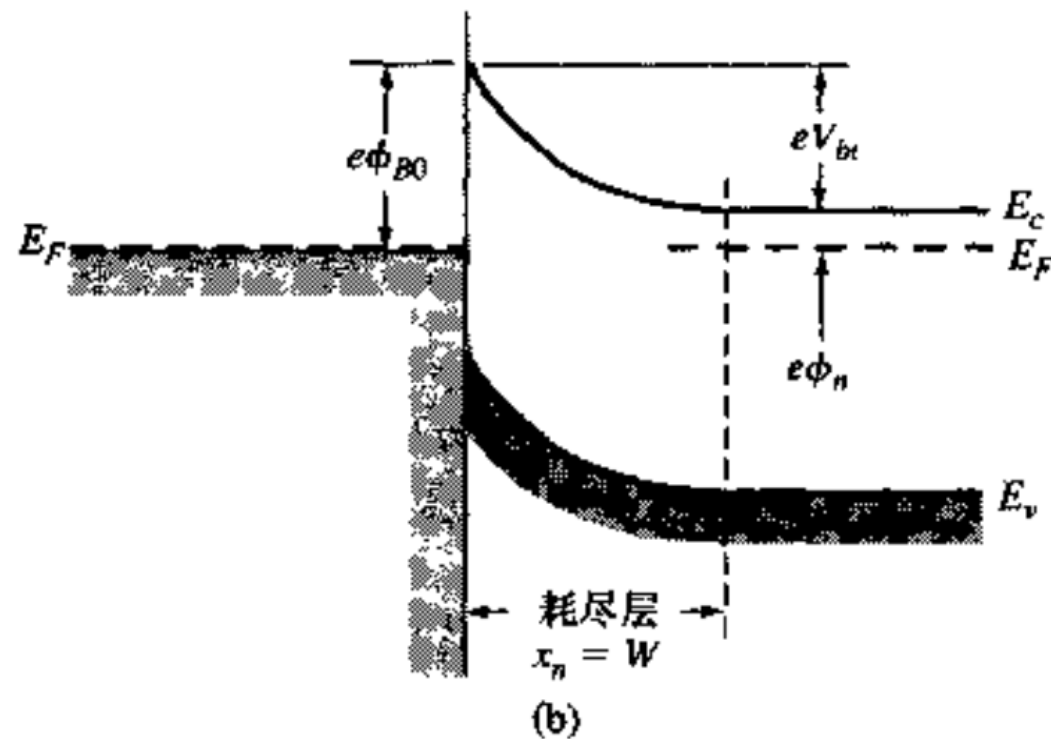
Advantages of MBE for InP-based HBT growth

- *High p-doping to $1E20\text{ cm}^{-3}$ and high n-doping to $5E19\text{ cm}^{-3}$*
- *Excellent thickness and interface control*
- *Easy to install various sensors for real-time monitoring*
- *Low background doping*
- *Low safety overhead*

IntelliEPI's Approaches in HBT development

- | | |
|---|--------------|
| • <i>Used multi-wafers 4x4in production MBE systems (9x4in)</i> | 12/99 |
| • <i>Installed sensors to monitor composition, temp., and surface</i> | 01/00 |
| • <i>Demonstrated reproducible and efficient P-cell operation</i> | 03/00 |
| • <i>Established safety protocol in P-MBE system R&M</i> | 06/00 |
| • <i>Delivered volume InP-based structures to customers</i> | 06/00 |
| • <i>Correlated processing results with in situ data</i> | 12/00 |
| • <i>Improved epitaxial growth based on correlations</i> | 03/01 |

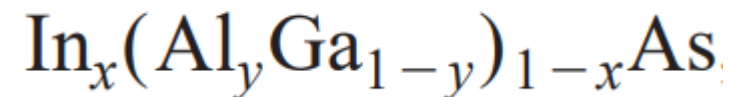
$$N_A \leq 10^{20}\text{ cm}^{-3}$$
$$N_D \leq 5 * 10^{19}\text{ cm}^{-3}$$



$$E_c - E_F = kT \ln\left(\frac{N_c}{N_d}\right)$$

$$R_c \propto e^{\frac{2\sqrt{\epsilon_s m_n^*}}{\hbar} \frac{\phi_{B0} - \phi_n}{\sqrt{N_d}}}$$

four $\text{In}_{0.52-x}\text{Al}_x\text{Ga}_y\text{As}_{0.48-y}$ based bulk layers with a fixed layer thickness as 3 nm and four different bandgap wavelengths at 1, 1.2, 1.4, and 1.6 μm , respectively. Such design can minimize the probability of hole trapping in the interface of hetero-structures with bandgap discontinuity, which is an issue for APD operated at the high-gain and high-power regimes [17]. High-power performance is an important characteristic for the modern APD based receiver under burst-mode operation [6], which needs to tolerate the significant variation in the launched optical power and sustain the high-speed performance.



$$1.519 + 1.36y - 1.584x + 0.55xy + 0.22y^2 + 0.475x^2$$

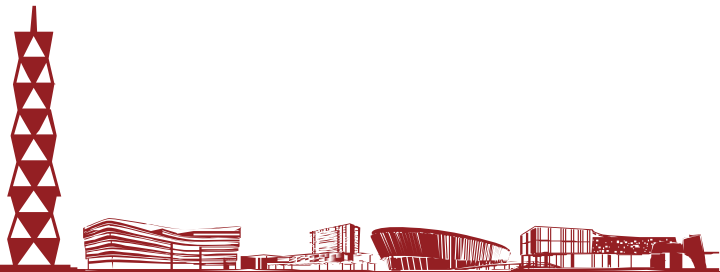
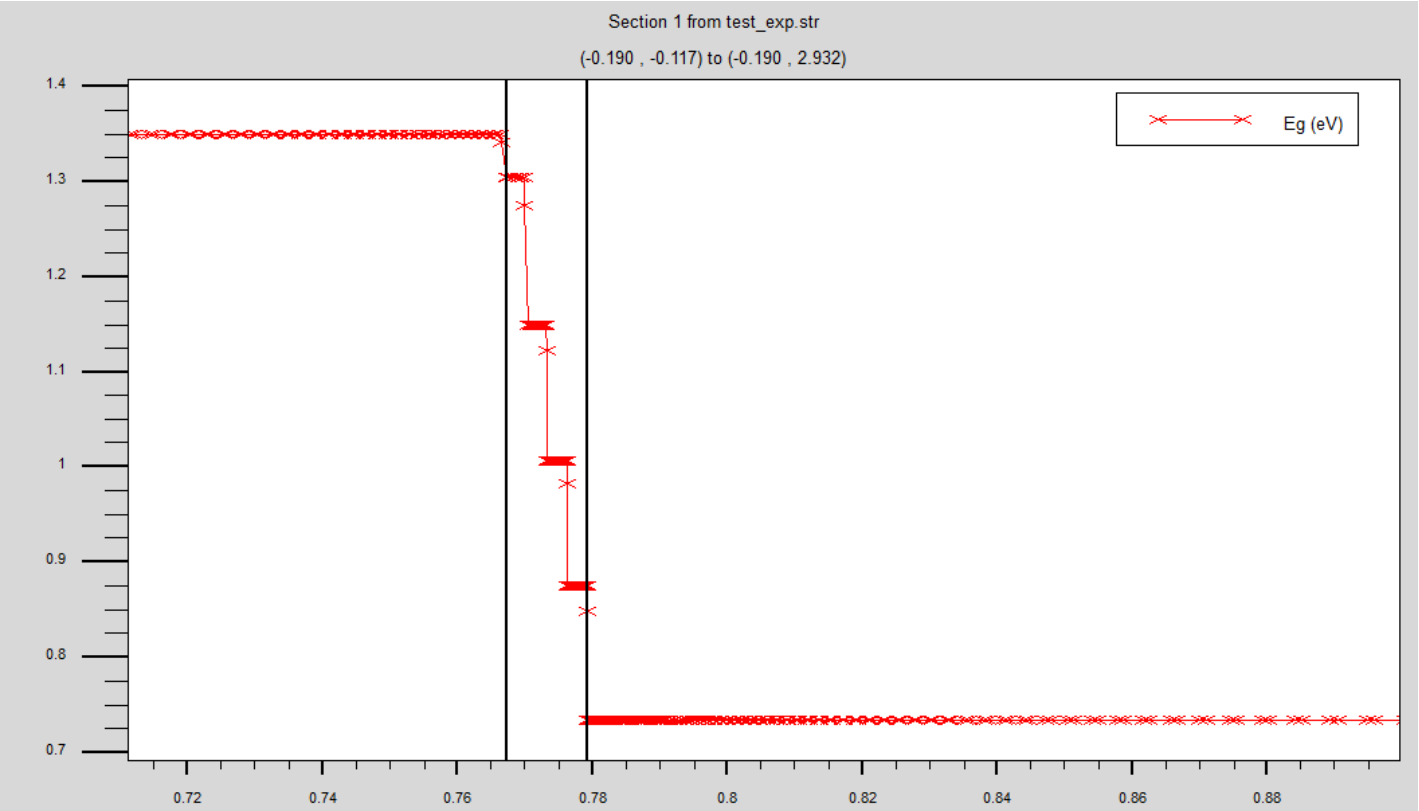
Material	Wavelength(um)
In0.61Al0.04Ga0.35As	1
In0.58Al0.03Ga0.39As	1.2
In0.55Al0.06Ga0.39As	1.4
In0.52Al0.12Ga0.36As	1.6



Graded Band

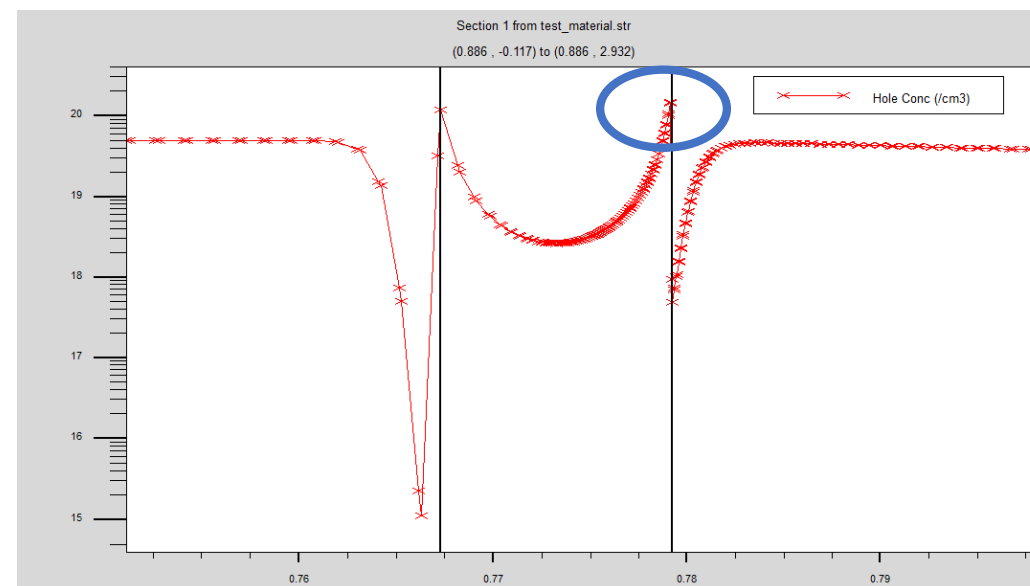
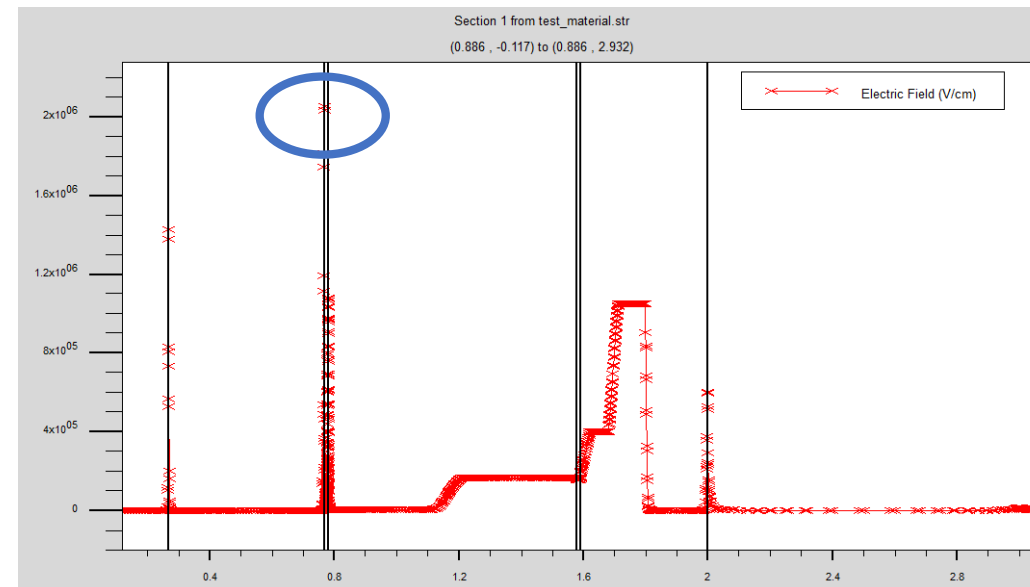
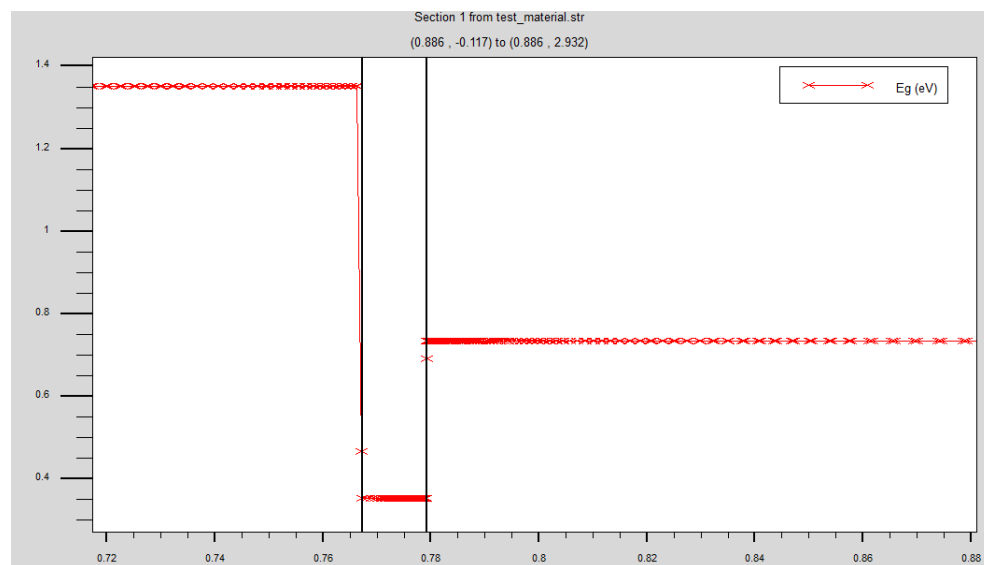


Material	Wavelength(um)
In0.2Al0.500Ga0.300As	1
In0.2Al0.367Ga0.433As	1.2
In0.2Al0.234Ga0.566As	1.4
In0.2Al0.100Ga0.700As	1.6



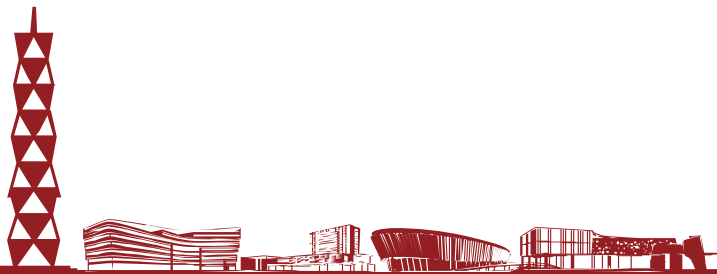
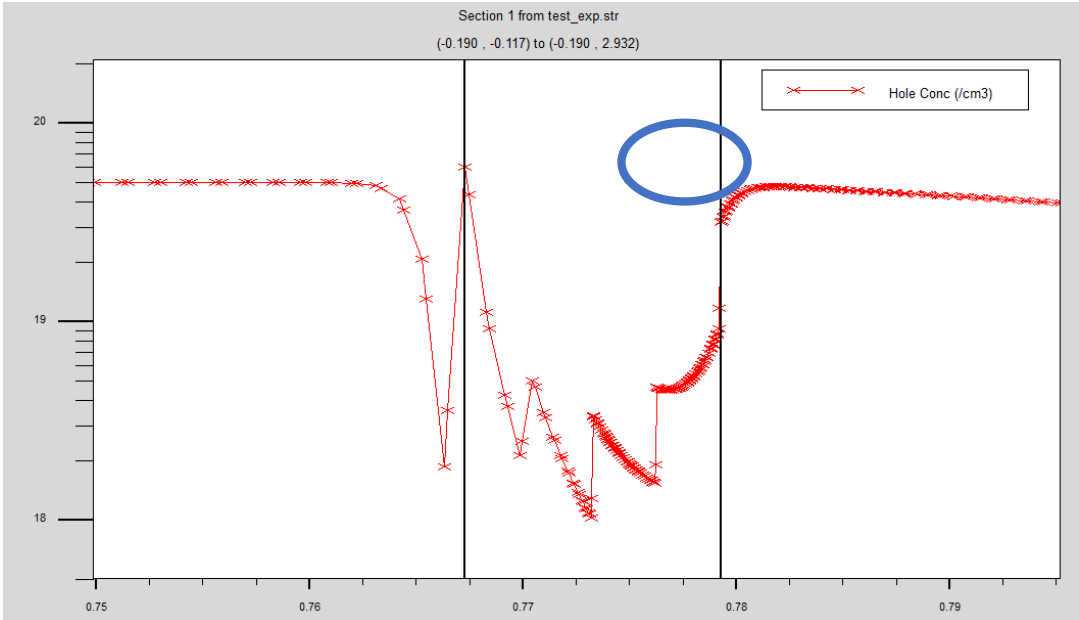
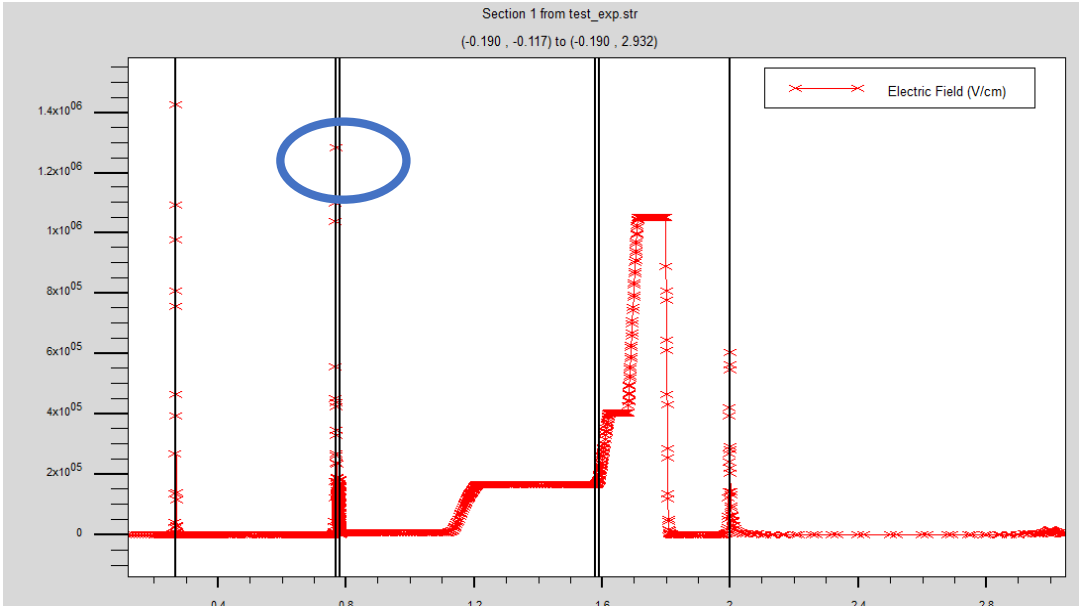
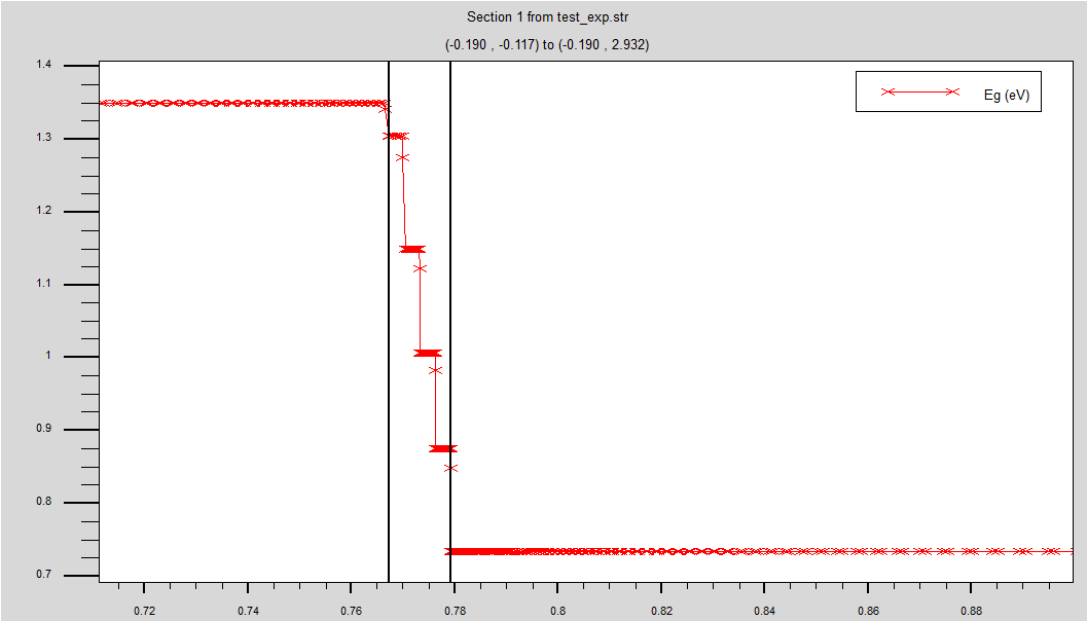


Discontinuity of E_g





Continuity of E_g

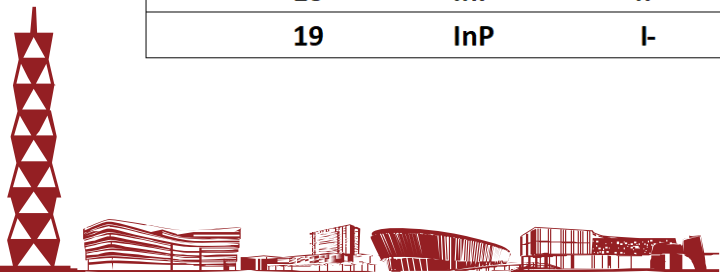
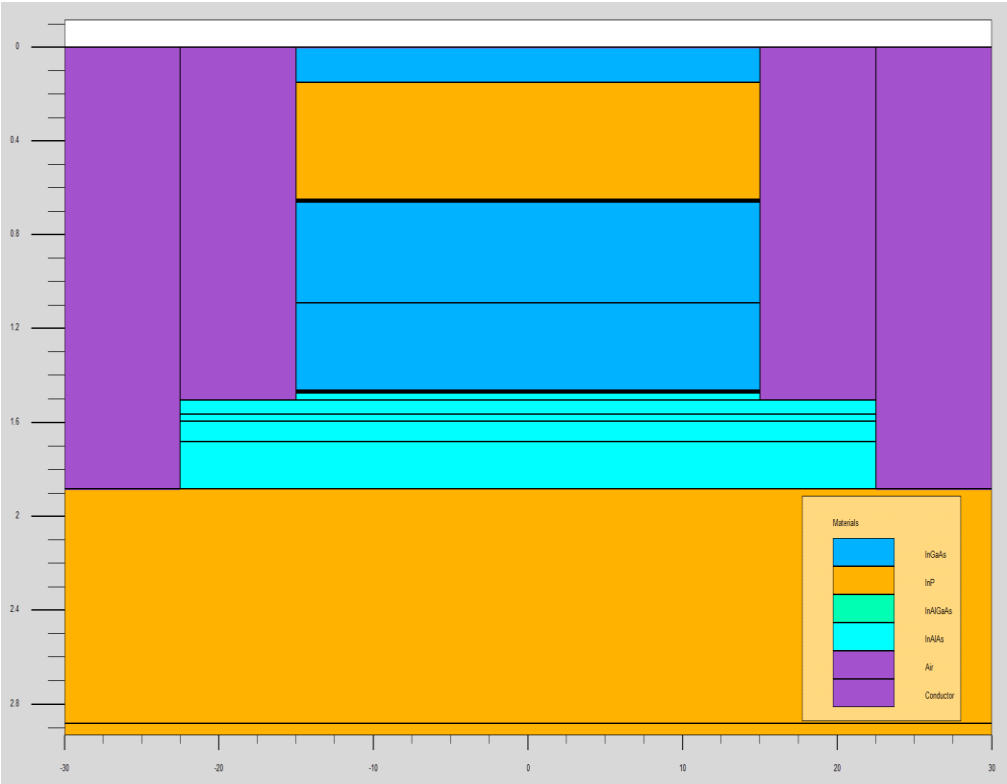




Initial Value

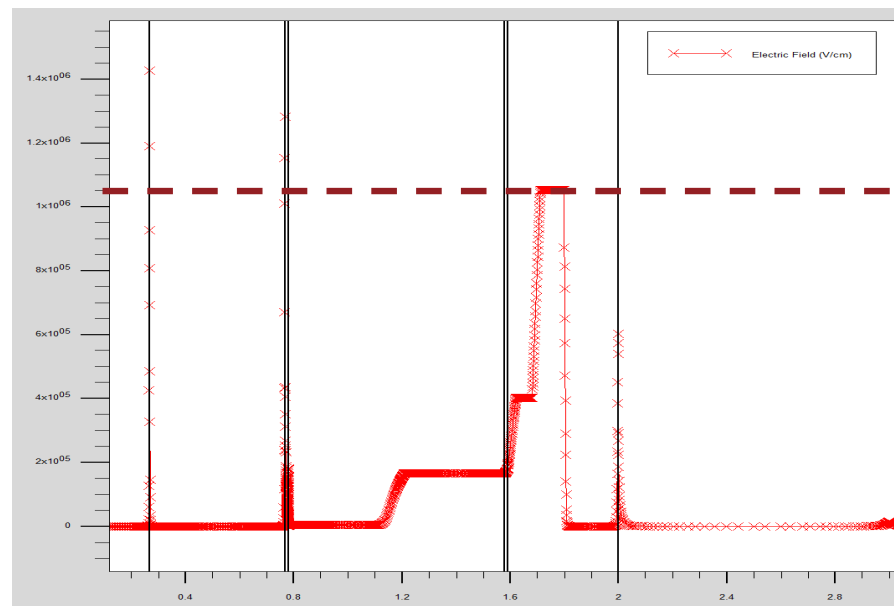
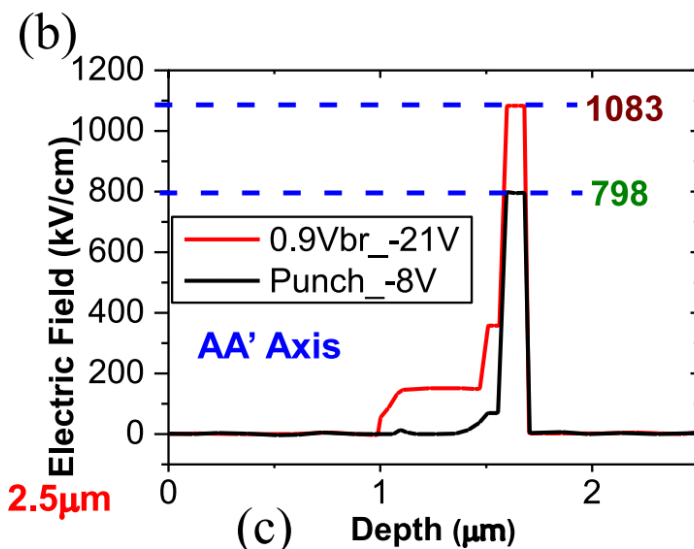


Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	2.00E+19	150
2	InP	p+	Contact	2.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	6.00E+16	3
4	In0.2Al0.367GaAs	p-	Graded Band	6.00E+16	3
5	In0.2Al0.234GaAs	p-	Graded Band	6.00E+16	3
6	In0.2Al0.100GaAs	p-	Graded Band	6.00E+16	3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	0.00E+00	370
9	In0.2Al0.100GaAs	I-	Graded Band	0.00E+00	3
10	In0.2Al0.234GaAs	I-	Graded Band	0.00E+00	3
11	In0.2Al0.367GaAs	I-	Graded Band	0.00E+00	3
12	In0.2Al0.500GaAs	I-	Graded Band	0.00E+00	3
13	In0.52Al0.48As	p-	Charge	5.00E+17	30
14	In0.52Al0.48As	I-	Field Buffer	0.00E+00	60
15	In0.52Al0.48As	p+	Charge	1.50E+18	30
16	In0.52Al0.48As	I-	Multiplication	0.00E+00	88
17	In0.52Al0.48As	n-	Contact	1.00E+19	200
18	InP	n-	Contact	1.00E+19	1000
19	InP	I-	Buffer	0.00E+00	50

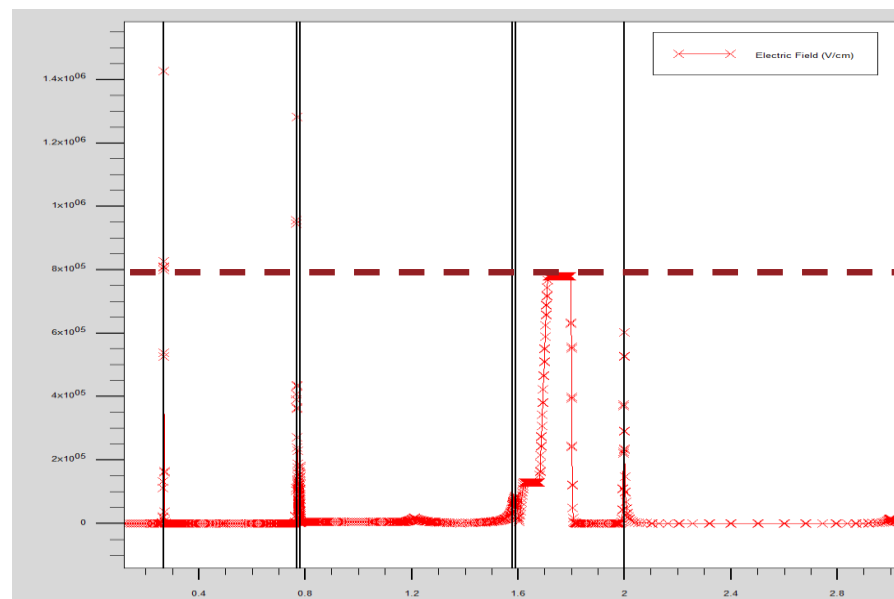




Initial Value

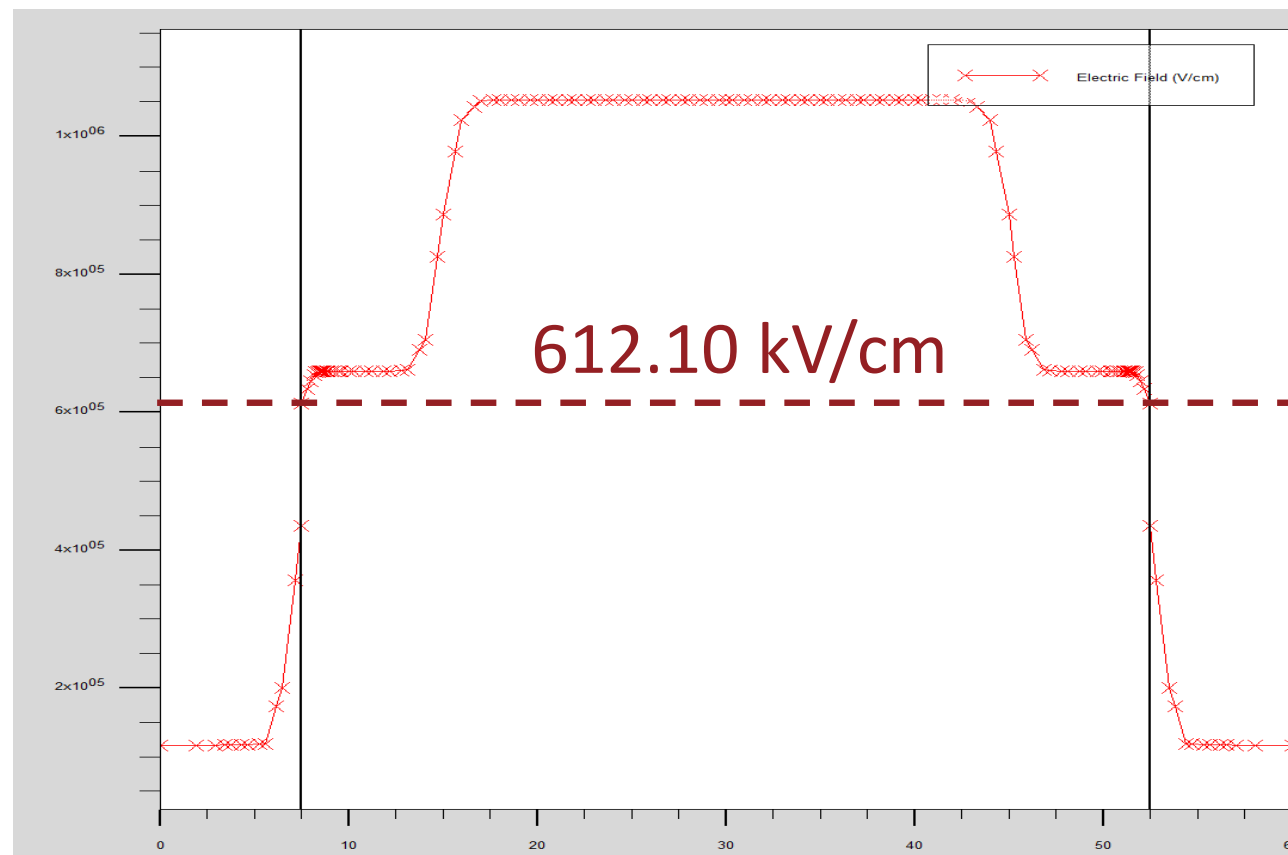
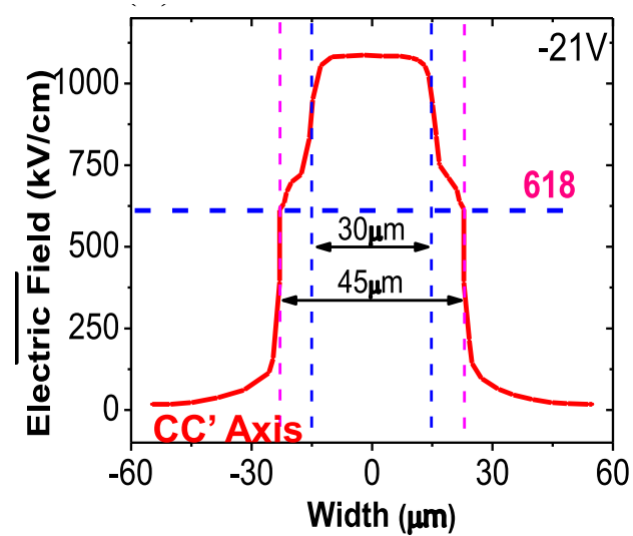


0.9Vbr_-21V:
1052.6 kV/cm



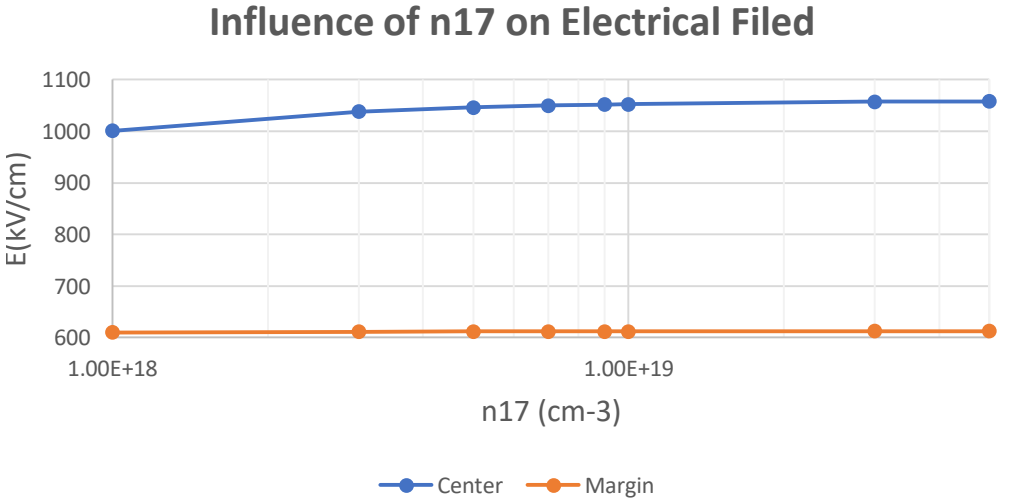
Punch_-8V:
779.88 kV/cm

Initial Value



Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	5.00E+19	150
2	InP	p+	Contact	5.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	5.00E+19	3
4	In0.2Al0.367GaAs	p-	Graded Band	5.00E+19	3
5	In0.2Al0.234GaAs	p-	Graded Band	5.00E+19	3
6	In0.2Al0.100GaAs	p-	Graded Band	5.00E+19	3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	0.00E+00	370
9	In0.2Al0.100GaAs	I-	Graded Band	0.00E+00	3
10	In0.2Al0.234GaAs	I-	Graded Band	0.00E+00	3
11	In0.2Al0.367GaAs	I-	Graded Band	0.00E+00	3
12	In0.2Al0.500GaAs	I-	Graded Band	0.00E+00	3
13	In0.52Al0.48As	p-	Charge	5.00E+17	3
14	In0.52Al0.48As	I-	Field Buffer	0.00E+00	0
15	In0.52Al0.48As	p+	Charge	1.50E+18	30
16	In0.52Al0.48As	I-	Multiplication	0.00E+00	88
17	In0.52Al0.48As	n-	Contact	n17	200
18	InP	n-	Contact	1.00E+19	1000
19	InP	I-	Buffer	0.00E+00	50

n17	1.00E+18	3.00E+18	5.00E+18	7.00E+18	9.00E+18	1.00E+19	3.00E+19	5.00E+19
Center	1001.1	1038.1	1046.2	1049.8	1051.8	1052.6	1057.1	1058.1
Margin	610.14	611.62	612.02	611.98	612.18	612.12	612.4	612.52

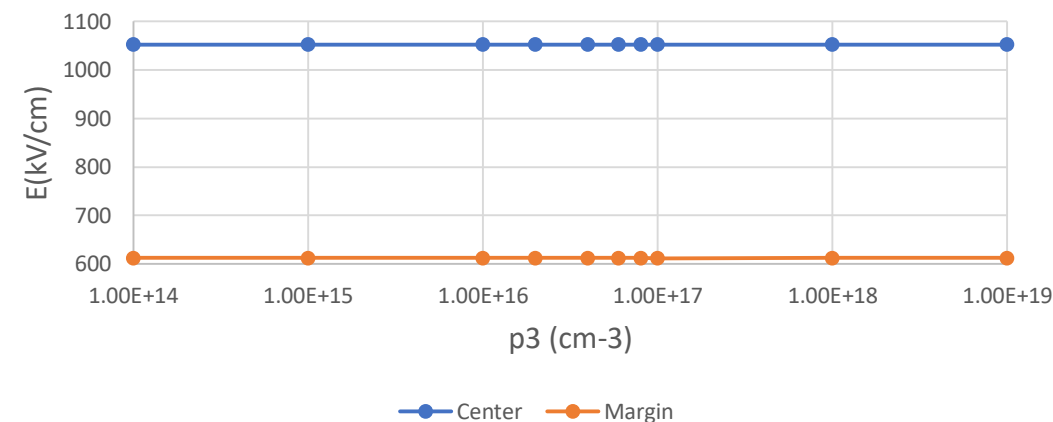


Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	5.00E+19	150
2	InP	p+	Contact	5.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	p3	3
4	In0.2Al0.367GaAs	p-	Graded Band		3
5	In0.2Al0.234GaAs	p-	Graded Band		3
6	In0.2Al0.100GaAs	p-	Graded Band		3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	0.00E+00	370
9	In0.2Al0.100GaAs	I-	Graded Band	0.00E+00	3
10	In0.2Al0.234GaAs	I-	Graded Band	0.00E+00	3
11	In0.2Al0.367GaAs	I-	Graded Band	0.00E+00	3
12	In0.2Al0.500GaAs	I-	Graded Band	0.00E+00	3
13	In0.52Al0.48As	p-	Charge	5.00E+17	30

14	In0.52Al0.48As	I-	Field Buffer	0.00E+00	60
15	In0.52Al0.48As	p+	Charge	1.50E+18	30
16	In0.52Al0.48As	I-	Multiplication	0.00E+00	88
17	In0.52Al0.48As	n-	Contact	1.00E+19	200
18	InP	n-	Contact	1.00E+19	1000
19	InP	I-	Buffer	0.00E+00	50

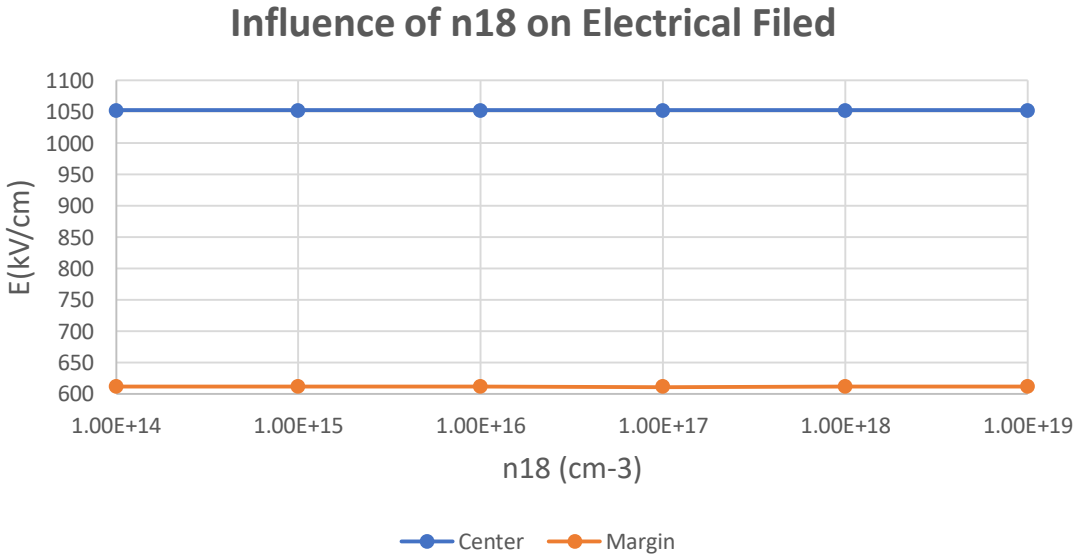
p3	1.00E+14	1.00E+15	1.00E+16	2.00E+16	4.00E+16	6.00E+16	8.00E+16	1.00E+17	1.00E+18	1.00E+19
Center	1052.6	1052.6	1052.6	1052.6	1052.6	1052.6	1052.6	1052.6	1052.6	1052.6
Margin	612.16	612.18	612.2	612.22	612.14	612.26	612.2	612.12	612.18	612.24

Influence of p3 on Electrical Filed



Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	5.00E+19	150
2	InP	p+	Contact	5.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	1.00E+17	3
4	In0.2Al0.367GaAs	p-	Graded Band	1.00E+17	3
5	In0.2Al0.234GaAs	p-	Graded Band	1.00E+17	3
6	In0.2Al0.100GaAs	p-	Graded Band	1.00E+17	3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	0.00E+00	370
9	In0.2Al0.100GaAs	I-	Graded Band	0.00E+00	3
10	In0.2Al0.234GaAs	I-	Graded Band	0.00E+00	3
11	In0.2Al0.367GaAs	I-	Graded Band	0.00E+00	3
12	In0.2Al0.500GaAs	I-	Graded Band	0.00E+00	3
13	In0.52Al0.48As	p-	Charge	5.00E+17	30
14	In0.52Al0.48As	I-	Field Buffer	0.00E+00	6
15	In0.52Al0.48As	p+	Charge	1.50E+18	70
16	In0.52Al0.48As	I-	Multiplication	0.00E+00	88
17	In0.52Al0.48As	n-	Contact	1.00E+19	200
18	InP	n-	Contact	n18	1000
19	InP	I-	Buffer	0.00E+00	50

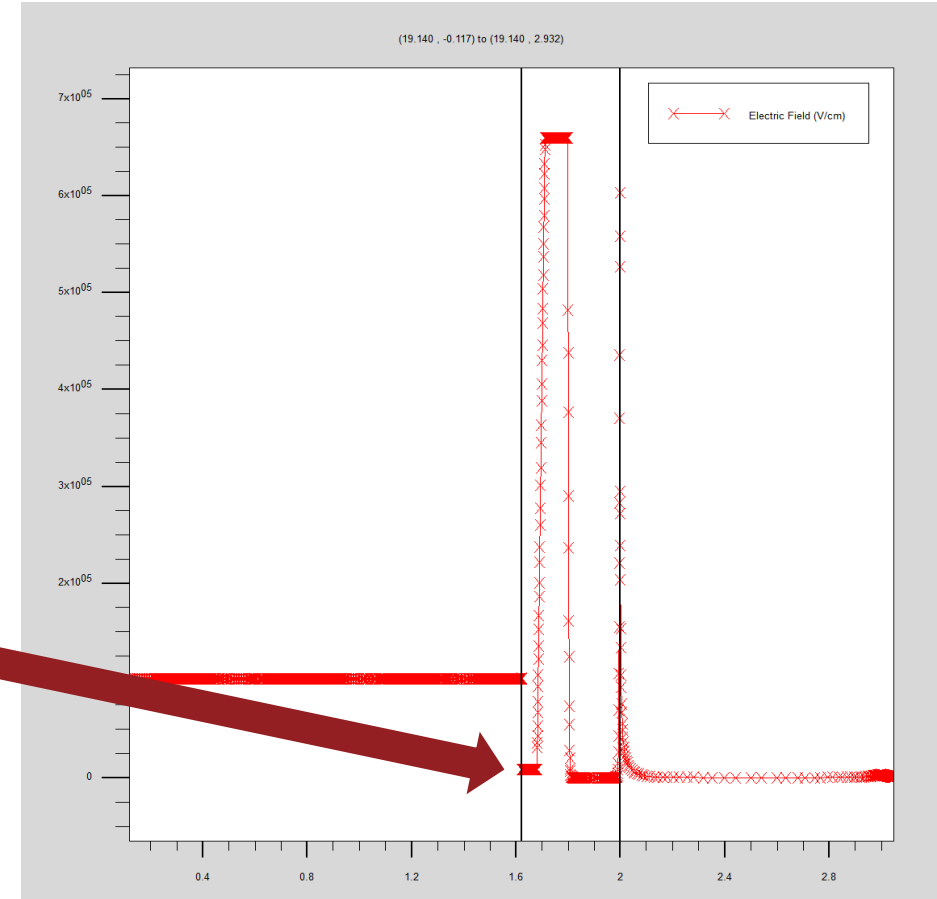
n18	1.00E+14	1.00E+15	1.00E+16	1.00E+17	1.00E+18	1.00E+19
Center	1052.6	1052.6	1.05E+03	1.05E+03	1052.6	1052.6
Margin	612.21	612.12	612.24	612.03	612.24	612.14





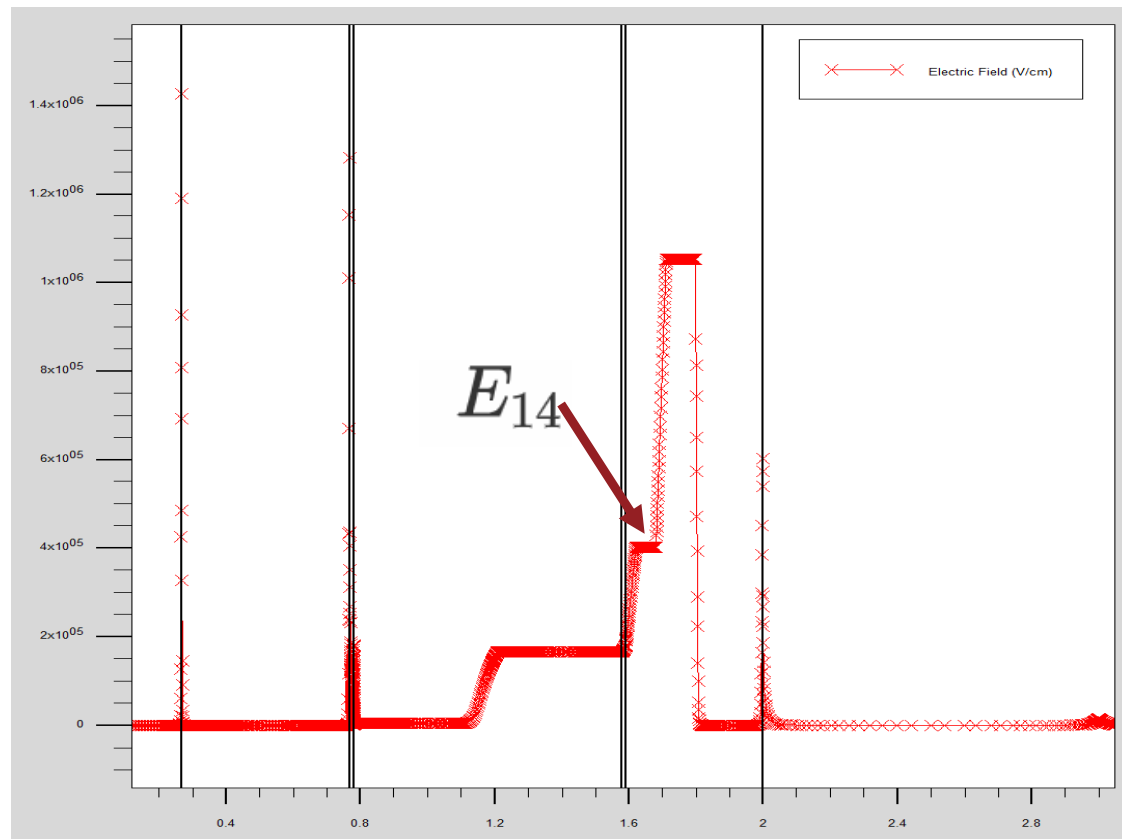
Dual charge layer

Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	2.00E+19	150
2	InP	p+	Contact	2.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	6.00E+16	3
4	In0.2Al0.367GaAs	p-	Graded Band	6.00E+16	3
5	In0.2Al0.234GaAs	p-	Graded Band	6.00E+16	3
6	In0.2Al0.100GaAs	p-	Graded Band	6.00E+16	3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	0.00E+00	370
9	In0.2Al0.100GaAs	I-	Graded Band	0.00E+00	3
10	In0.2Al0.234GaAs	I-	Graded Band	0.00E+00	3
11	In0.2Al0.367GaAs	I-	Graded Band	0.00E+00	3
12	In0.2Al0.500GaAs	I-	Graded Band	0.00E+00	3
13	In0.52Al0.48As	p-	Charge	5.00E+17	30
14	In0.52Al0.48As	I-	Field Buffer	0.00E+00	60
15	In0.52Al0.48As	p+	Charge	1.50E+18	30
16	In0.52Al0.48As	I-	Multiplication	0.00E+00	88
17	In0.52Al0.48As	n-	Contact	1.00E+19	200
18	InP	n-	Contact	1.00E+19	1000
19	InP	I-	Buffer	0.00E+00	50

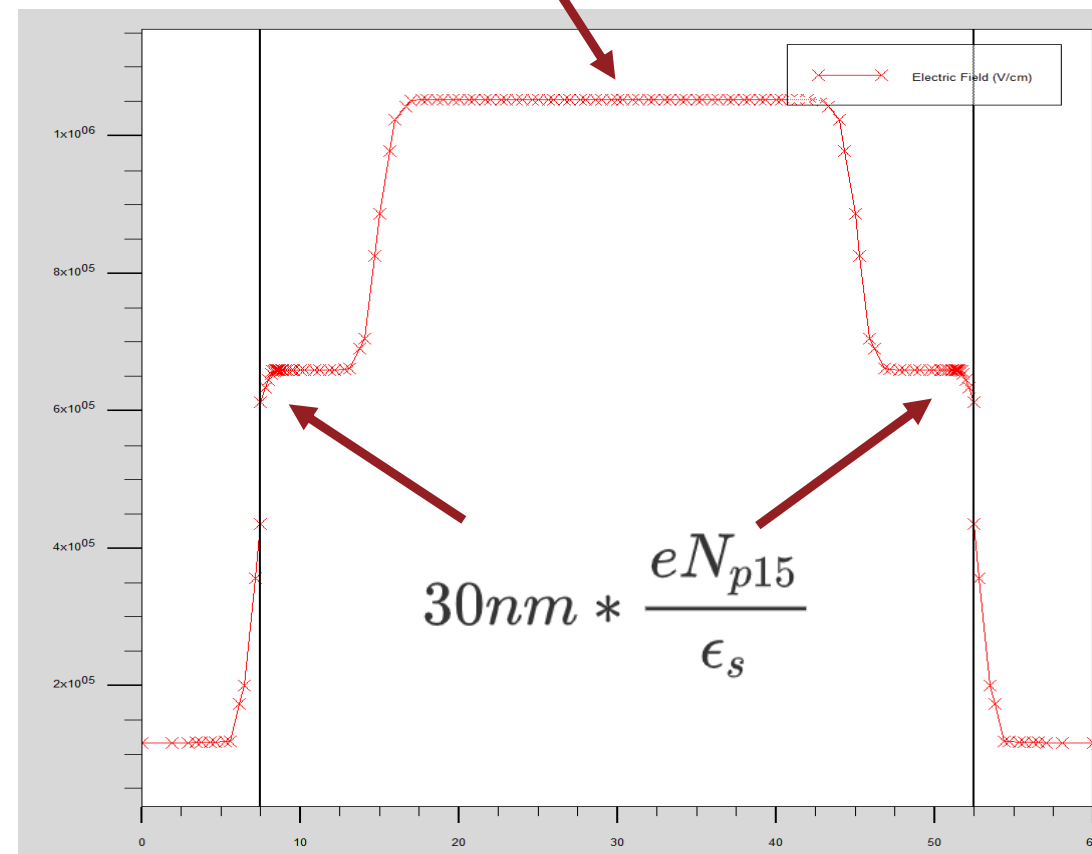




Dual charge layer



$$E_{14} + 30nm * \frac{eN_{p15}}{\epsilon_s}$$



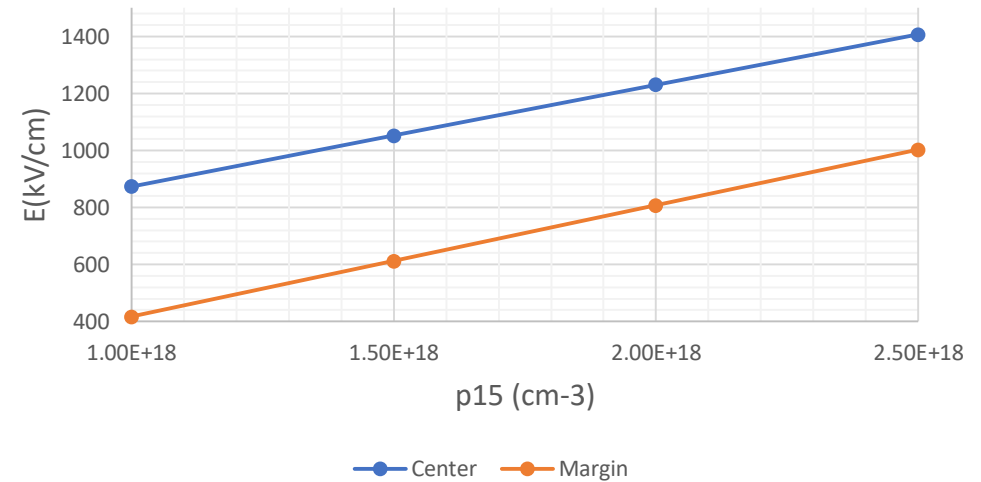
Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	5.00E+19	150
2	InP	p+	Contact	5.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	1.00E+17	3
4	In0.2Al0.367GaAs	p-	Graded Band	1.00E+17	3
5	In0.2Al0.234GaAs	p-	Graded Band	1.00E+17	3
6	In0.2Al0.100GaAs	p-	Graded Band	1.00E+17	3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	0.00E+00	370
9	In0.2Al0.100GaAs	I-	Graded Band	0.00E+00	3
10	In0.2Al0.234GaAs	I-	Graded Band	0.00E+00	3
11	In0.2Al0.367GaAs	I-	Graded Band	0.00E+00	3
12	In0.2Al0.500GaAs	I-	Graded Band	0.00E+00	3
13	In0.52Al0.48As	p-	Charge	5.00E+17	30

14	In0.52Al0.48As	I-	Field Buffer	0.00E+00	60
15	In0.52Al0.48As	p+	Charge	p15	30
16	In0.52Al0.48As	I-	Multiplication	0.00E+00	88
17	In0.52Al0.48As	n-	Contact	1.00E+19	200

18	InP	n-	Contact	1.00E+17	1000
19	InP	I-	Buffer	0.00E+00	50

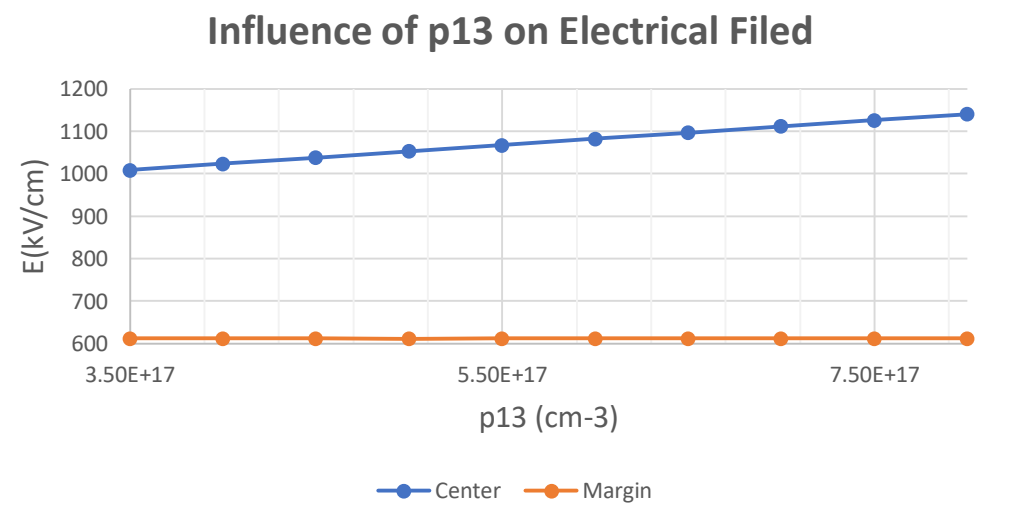
p15	1.00E+18	1.50E+18	2.00E+18	2.50E+18
Center	873.6	1052.6	1.23E+03	1407.8
Margin	416.6	612.22	807.62	1003.1

Influence of p15 on Electrical Filed



Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	5.00E+19	150
2	InP	p+	Contact	5.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	1.00E+17	3
4	In0.2Al0.367GaAs	p-	Graded Band	1.00E+17	3
5	In0.2Al0.234GaAs	p-	Graded Band	1.00E+17	3
6	In0.2Al0.100GaAs	p-	Graded Band	1.00E+17	3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	0.00E+00	370
9	In0.2Al0.100GaAs	I-	Graded Band	0.00E+00	3
10	In0.2Al0.234GaAs	I-	Graded Band	0.00E+00	3
11	In0.2Al0.367GaAs	I-	Graded Band	0.00E+00	3
12	In0.2Al0.500GaAs	I-	Graded Band	0.00E+00	3
13	In0.52Al0.48As	p-	Charge	p13	30
14	In0.52Al0.48As	I-	Field Buffer	0.00E+00	60
15	In0.52Al0.48As	p+	Charge	1.50E+18	30
16	In0.52Al0.48As	I-	Multiplication	0.00E+00	88
17	In0.52Al0.48As	n-	Contact	1.00E+19	200
18	InP	n-	Contact	1.00E+17	1000
19	InP	I-	Buffer	0.00E+00	50

p13	3.50E+17	4.00E+17	4.50E+17	5.00E+17	5.50E+17	6.00E+17	6.50E+17	7.00E+17	7.50E+17	8.00E+17
Center	1008.3	1023.1	1037.8	1052.6	1067.3	1081.9	1096.6	1111.2	1125.8	1140.4
Margin	612.1	612.2	612.05	611.97	612.1	612.2	612.12	612.16	612.12	612.2





Structure B comparison

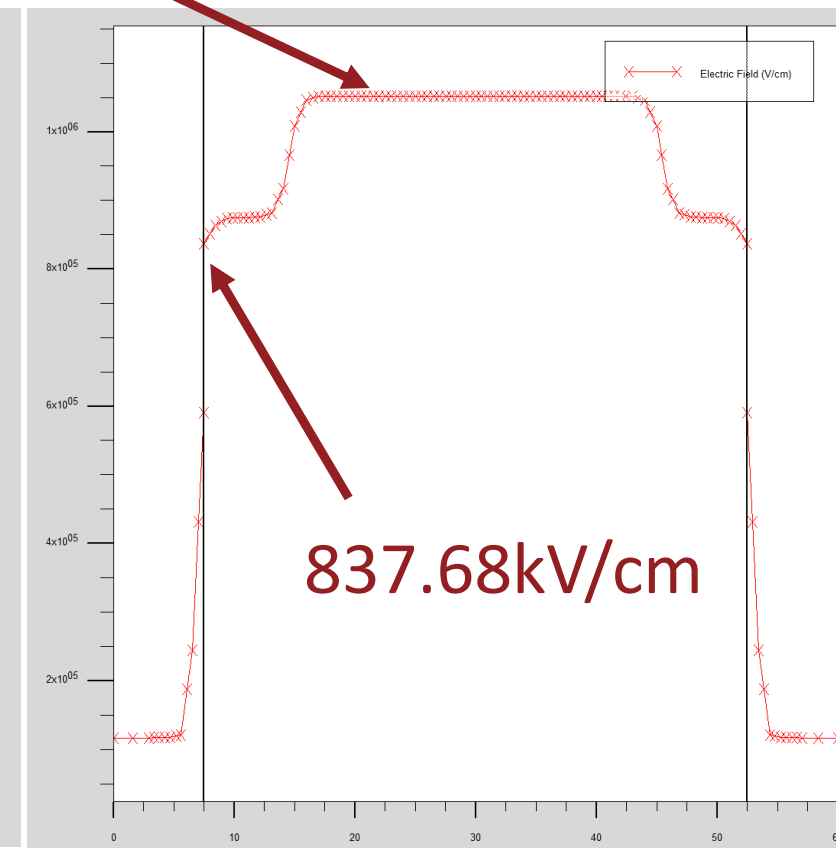
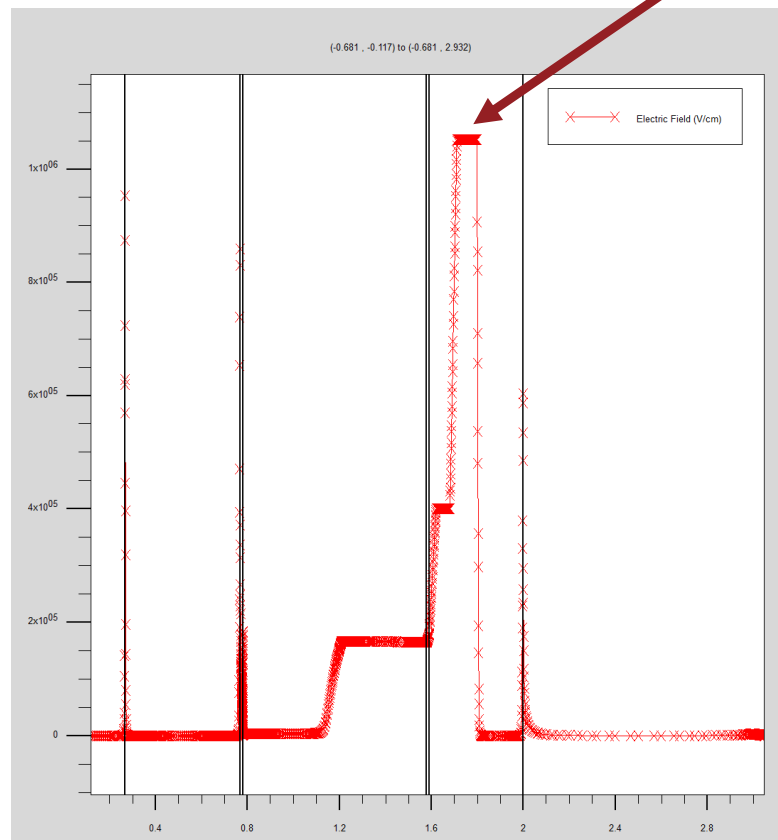
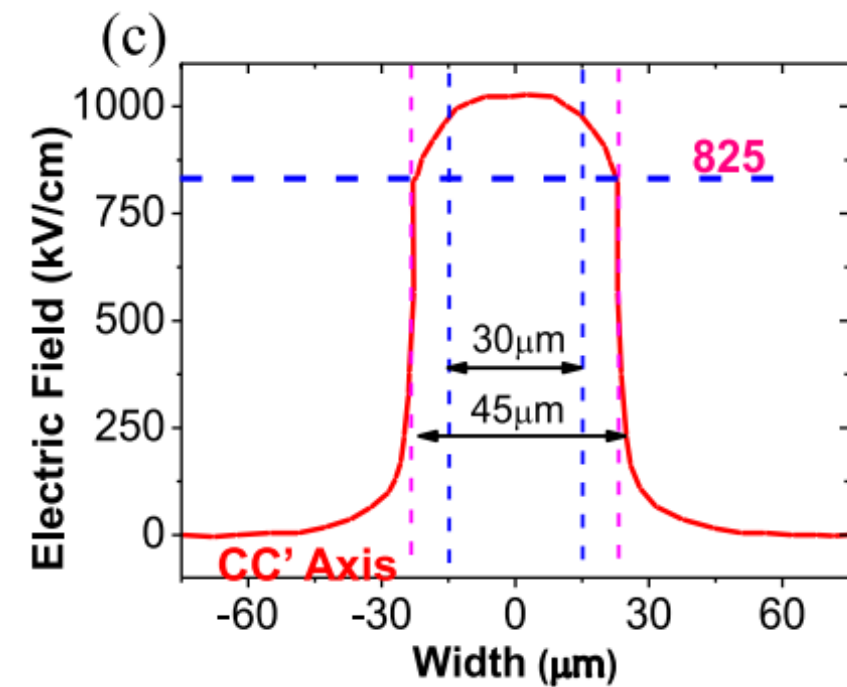


Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	2.00E+19	150
2	InP	p+	Contact	2.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	6.00E+16	3
4	In0.2Al0.367GaAs	p-	Graded Band	6.00E+16	3
5	In0.2Al0.234GaAs	p-	Graded Band	6.00E+16	3
6	In0.2Al0.100GaAs	p-	Graded Band	6.00E+16	3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	0.00E+00	370
9	In0.2Al0.100GaAs	I-	Graded Band	0.00E+00	3
10	In0.2Al0.234GaAs	I-	Graded Band	0.00E+00	3
11	In0.2Al0.367GaAs	I-	Graded Band	0.00E+00	3
12	In0.2Al0.500GaAs	I-	Graded Band	0.00E+00	3
13	In0.52Al0.48As	p-	Charge	5.00E+17	30
14	In0.52Al0.48As	I-	Field Buffer	0.00E+00	60
15	In0.52Al0.48As	p+	Charge	1.50E+18	30
16	In0.52Al0.48As	I-	Multiplication	0.00E+00	88
17	In0.52Al0.48As	n-	Contact	1.00E+19	200
18	InP	n-	Contact	1.00E+19	1000
19	InP	I-	Buffer	0.00E+00	50

Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	2.00E+19	150
2	InP	p+	Contact	2.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	6.00E+16	3
4	In0.2Al0.367GaAs	p-	Graded Band	6.00E+16	3
5	In0.2Al0.234GaAs	p-	Graded Band	6.00E+16	3
6	In0.2Al0.100GaAs	p-	Graded Band	6.00E+16	3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	0.00E+00	370
9	In0.2Al0.100GaAs	I-	Graded Band	0.00E+00	3
10	In0.2Al0.234GaAs	I-	Graded Band	0.00E+00	3
11	In0.2Al0.367GaAs	I-	Graded Band	0.00E+00	3
12	In0.2Al0.500GaAs	I-	Graded Band	0.00E+00	3
13	In0.52Al0.48As	p-	Charge	5.00E+17	30
14	In0.52Al0.48As	I-	Field Buffer	0.00E+00	60
15	In0.52Al0.48As	p+	Charge	1.50E+18	30
16	In0.52Al0.48As	I-	Multiplication	0.00E+00	88
17	In0.52Al0.48As	n-	Contact	1.00E+19	200
18	InP	n-	Contact	1.00E+19	1000
19	InP	I-	Buffer	0.00E+00	50



Structure B comparison





Structure C comparison

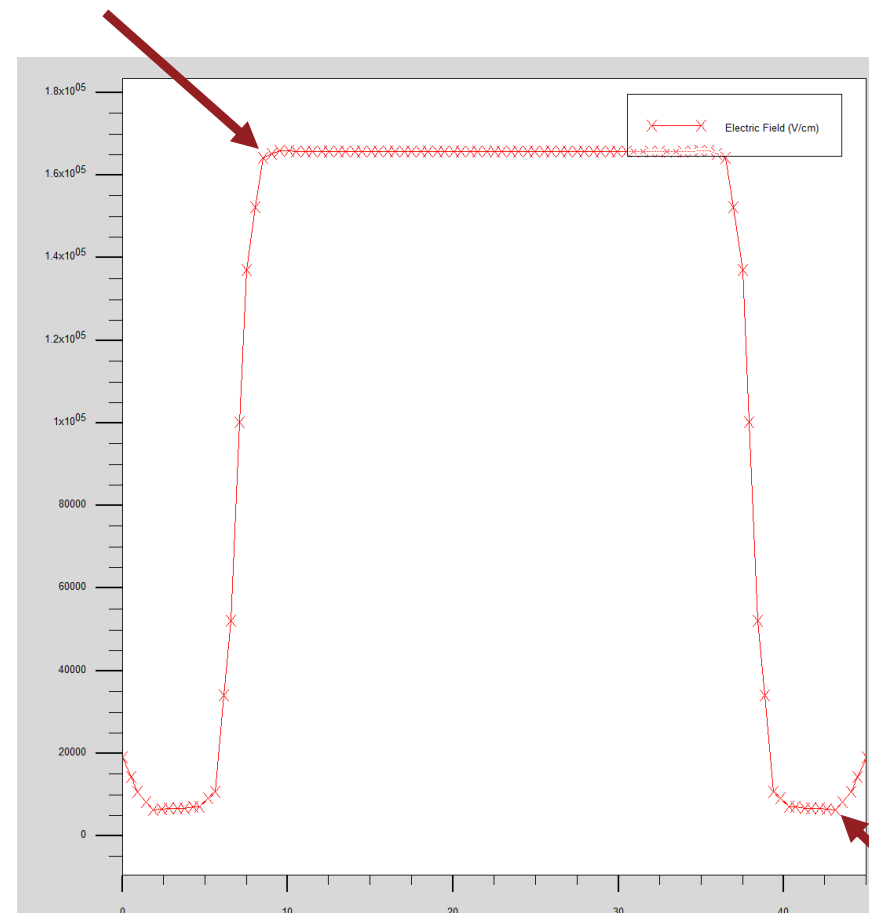
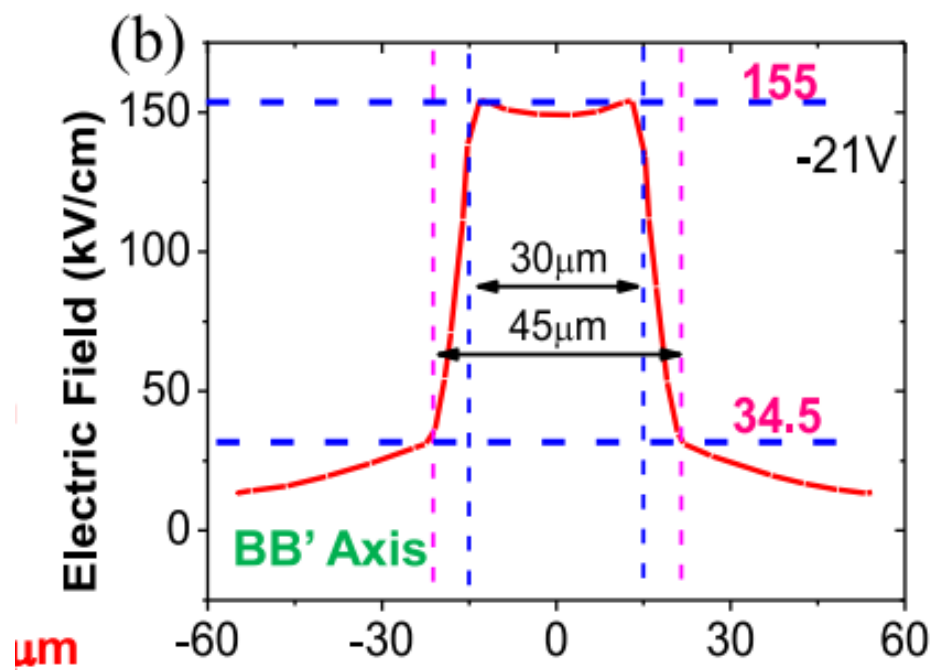


Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	2.00E+19	150
2	InP	p+	Contact	2.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	6.00E+16	3
4	In0.2Al0.367GaAs	p-	Graded Band	6.00E+16	3
5	In0.2Al0.234GaAs	p-	Graded Band	6.00E+16	3
6	In0.2Al0.100GaAs	p-	Graded Band	6.00E+16	3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	0.00E+00	370
9	In0.2Al0.100GaAs	I-	Graded Band	0.00E+00	3
10	In0.2Al0.234GaAs	I-	Graded Band	0.00E+00	3
11	In0.2Al0.367GaAs	I-	Graded Band	0.00E+00	3
12	In0.2Al0.500GaAs	I-	Graded Band	0.00E+00	3
13	In0.52Al0.48As	p-	Charge	5.00E+17	30
14	In0.52Al0.48As	I-	Field Buffer	0.00E+00	60
15	In0.52Al0.48As	p+	Charge	1.50E+18	30
16	In0.52Al0.48As	I-	Multiplication	0.00E+00	88
17	In0.52Al0.48As	n-	Contact	1.00E+19	200
18	InP	n-	Contact	1.00E+19	1000
19	InP	I-	Buffer	0.00E+00	50

Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	2.00E+19	150
2	InP	p+	Contact	2.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	6.00E+16	3
4	In0.2Al0.367GaAs	p-	Graded Band	6.00E+16	3
5	In0.2Al0.234GaAs	p-	Graded Band	6.00E+16	3
6	In0.2Al0.100GaAs	p-	Graded Band	6.00E+16	3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	0.00E+00	370
9	In0.2Al0.100GaAs	I-	Graded Band	0.00E+00	3
10	In0.2Al0.234GaAs	I-	Graded Band	0.00E+00	3
11	In0.2Al0.367GaAs	I-	Graded Band	0.00E+00	3
12	In0.2Al0.500GaAs	I-	Graded Band	0.00E+00	3
13	In0.52Al0.48As	p-	Charge	5.00E+17	30
14	In0.52Al0.48As	I-	Field Buffer	0.00E+00	60
15	In0.52Al0.48As	p+	Charge	1.50E+18	30
16	In0.52Al0.48As	I-	Multiplication	0.00E+00	88
17	In0.52Al0.48As	n-	Contact	1.00E+19	200
18	InP	n-	Contact	1.00E+19	1000
19	InP	I-	Buffer	0.00E+00	50

Structure C comparison

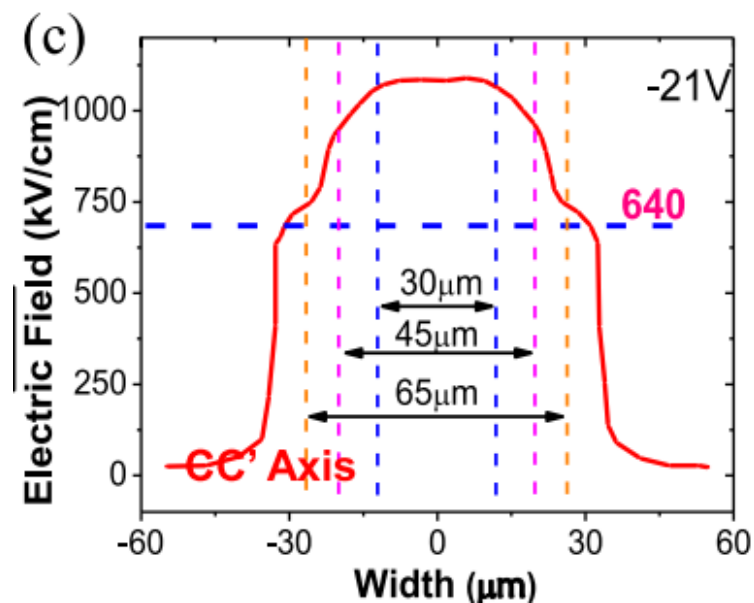
165.78kV/cm



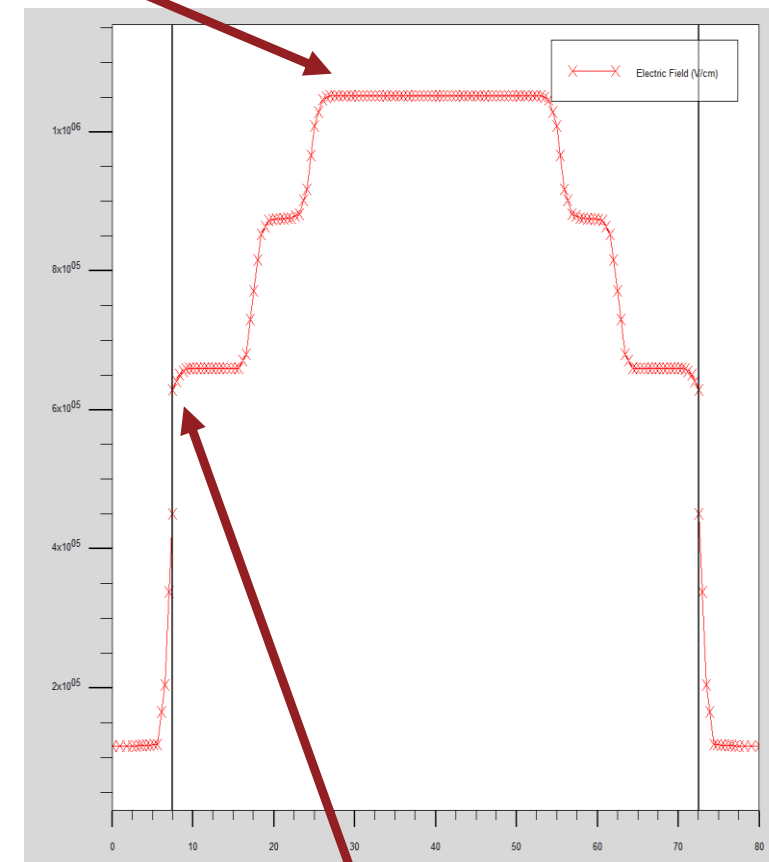
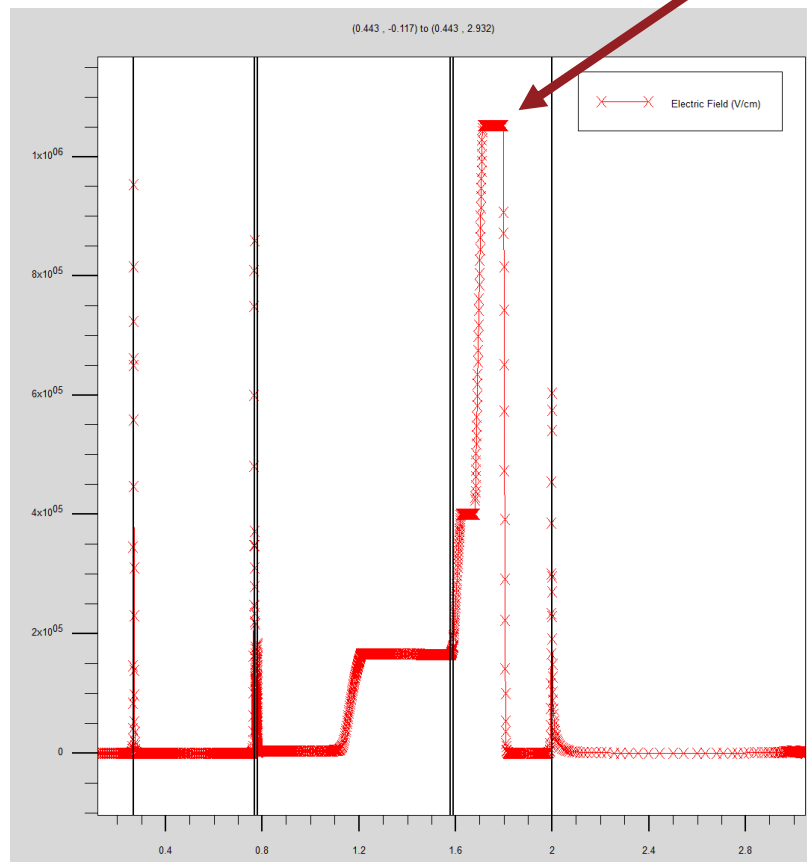
64kV/cm



Structure C comparison



1052.4kV/cm



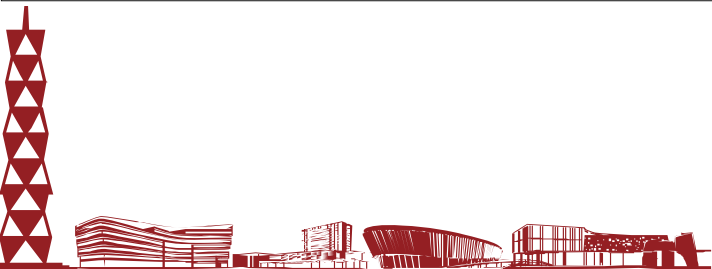
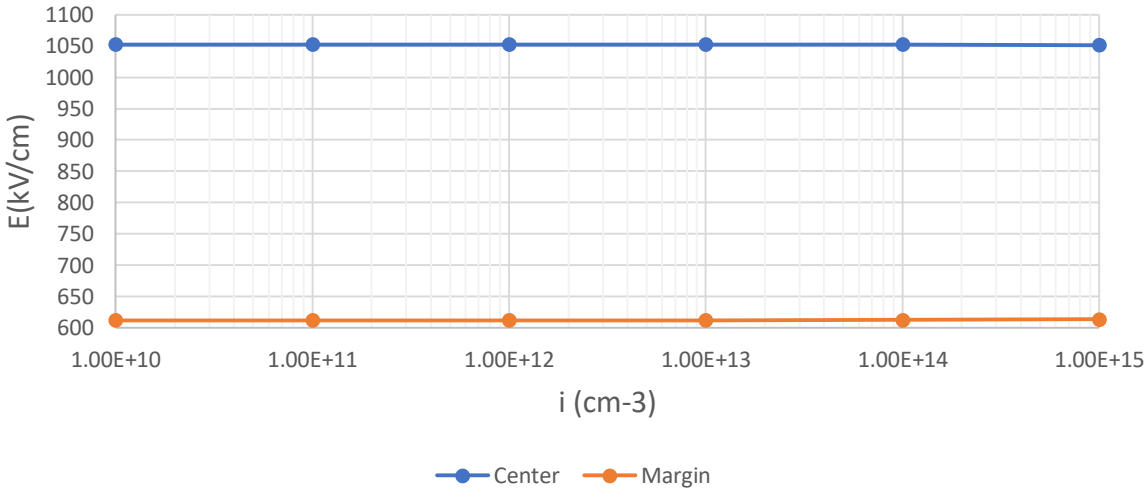
629.04kV/cm



Ind	Material	Dope	Name	Conc	Depth
1	In0.53Ga0.47As	p+	Contact	5.00E+19	150
2	InP	p+	Contact	5.00E+19	500
3	In0.2Al0.500GaAs	p-	Graded Band	1.00E+17	3
4	In0.2Al0.367GaAs	p-	Graded Band	1.00E+17	3
5	In0.2Al0.234GaAs	p-	Graded Band	1.00E+17	3
6	In0.2Al0.100GaAs	p-	Graded Band	1.00E+17	3
7	In0.53Ga0.47As	p+	Graded Absorber	graded	430
8	In0.53Ga0.47As	I-	Undoped Absorber	i	370
9	In0.2Al0.100GaAs	I-	Graded Band	i	3
10	In0.2Al0.234GaAs	I-	Graded Band	i	3
11	In0.2Al0.367GaAs	I-	Graded Band	i	3
12	In0.2Al0.500GaAs	I-	Graded Band	i	3
13	In0.52Al0.48As	p-	Charge	5.00E+17	30
14	In0.52Al0.48As	I-	Field Buffer	i	60
15	In0.52Al0.48As	p+	Charge	1.50E+18	30
16	In0.52Al0.48As	I-	Multiplication	i	88
17	In0.52Al0.48As	n-	Contact	1.00E+19	200
18	InP	n-	Contact	1.00E+17	1000
19	InP	I-	Buffer	i	50

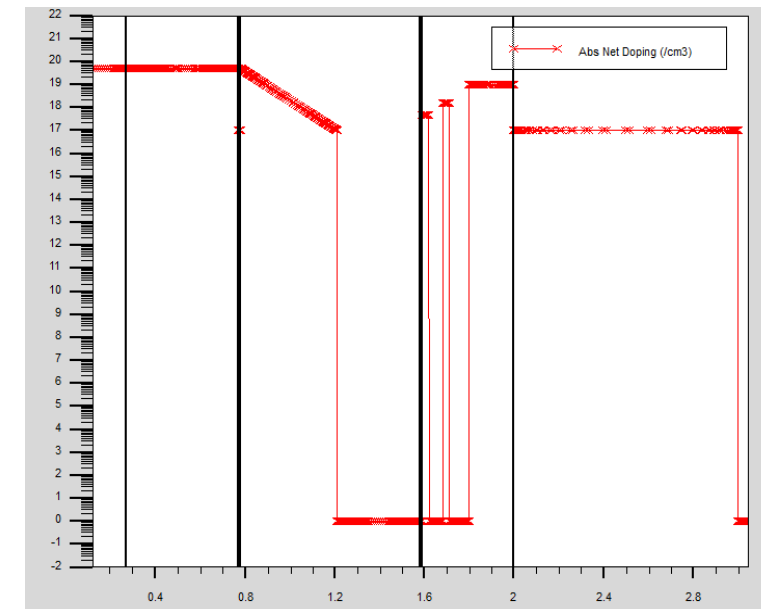
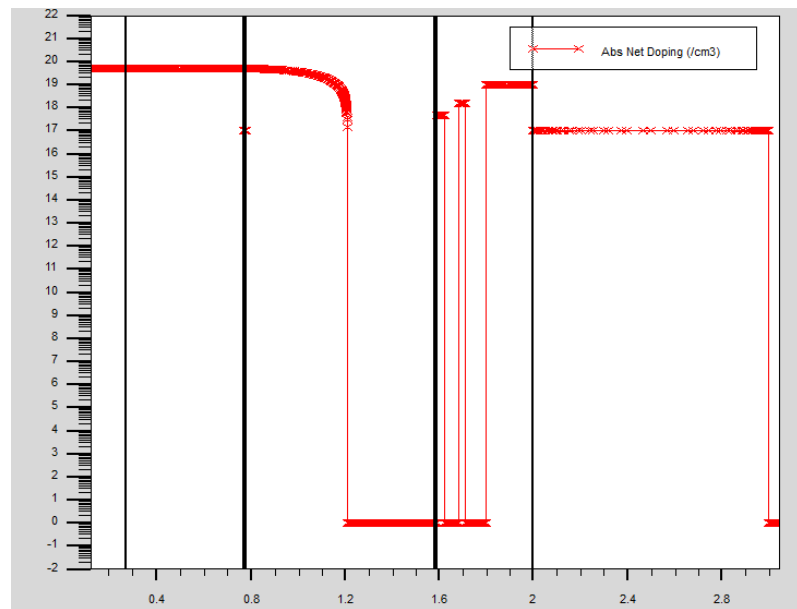
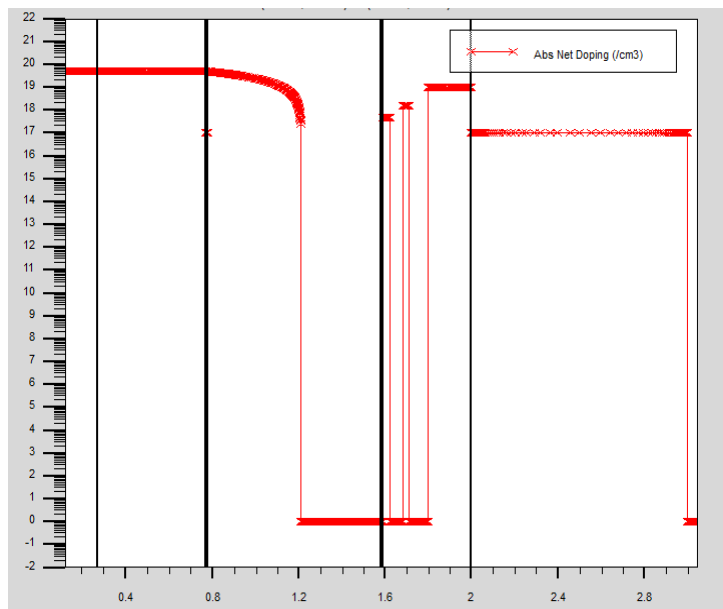
i	1.00E+10	1.00E+11	1.00E+12	1.00E+13	1.00E+14	1.00E+15
Center	1052.6	1052.6	1052.6	1052.6	1052.6	1051.8
Margin	612.16	612.11	612.26	612.22	612.56	613.72

Influence of i on Electrical Filed

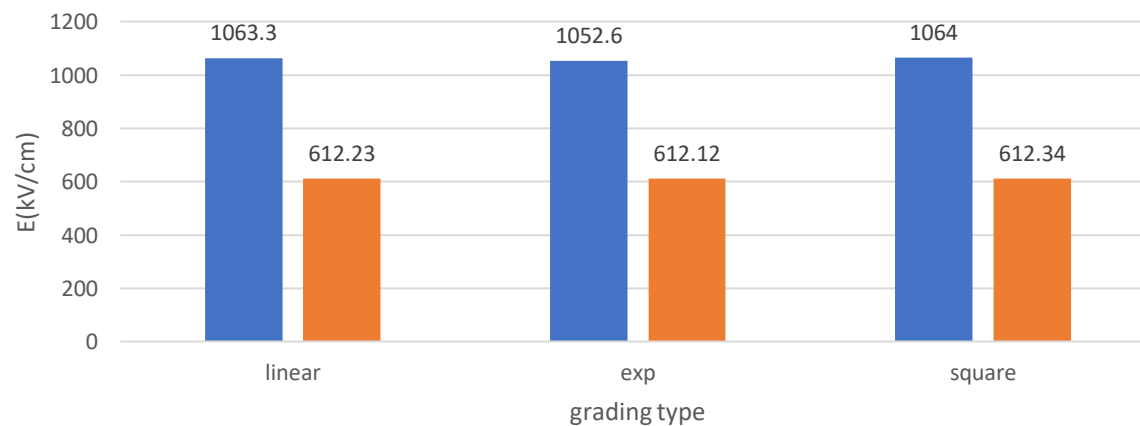




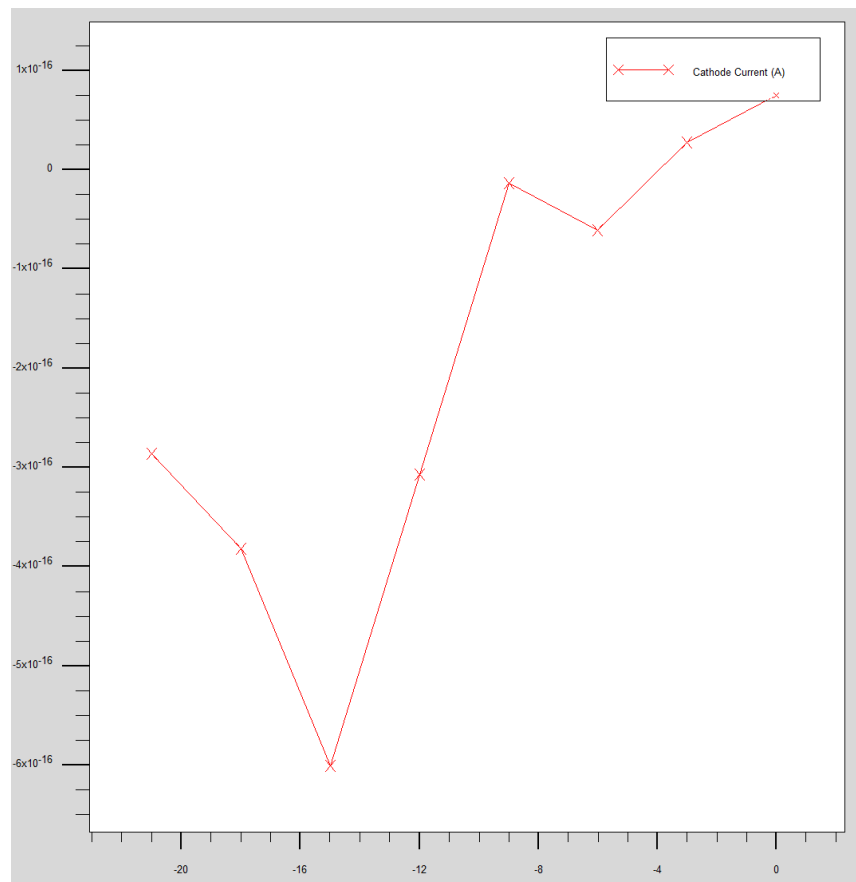
Graded doping type



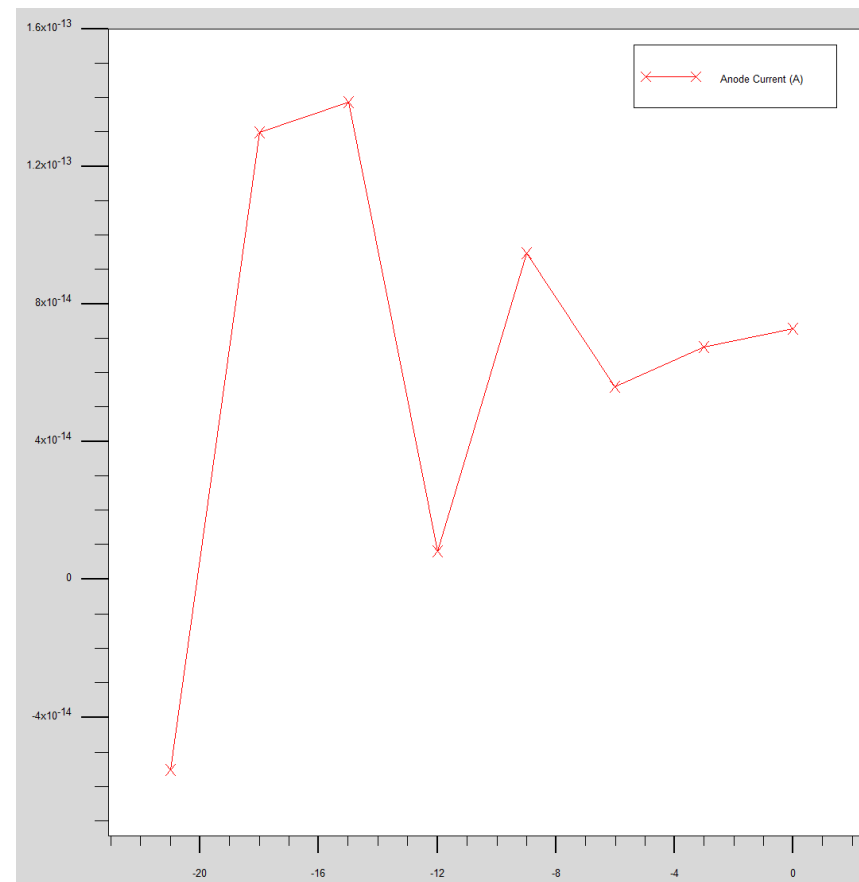
Influence of doping grade on Electrical Filed



$$J_{p,diff} = eD_p \frac{dp}{dx}$$



Dark Current



Light Current